

AMC1305x-Q1

High-Precision, Reinforced Isolated Delta-Sigma Modulators

1 Features

- Qualified for Automotive Applications
- AEC-Q100 Qualified with the Following Results:
 - Temperature Grade 1: -40°C to $+125^{\circ}\text{C}$
 - HBM ESD Classification Level 2
 - CDM ESD Classification Level C6
- Pin-Compatible Family With:
 - $\pm 50\text{-mV}$ or $\pm 250\text{-mV}$ Input Voltage Ranges
 - CMOS or LVDS Digital Interface Options
- Excellent DC Performance:
 - Offset Error: $\pm 50\ \mu\text{V}$ or $\pm 150\ \mu\text{V}$ (max)
 - Offset Drift: $1.3\ \mu\text{V}/^{\circ}\text{C}$ (max)
 - Gain Error: $\pm 0.3\%$ (max)
 - Gain Drift: $\pm 40\ \text{ppm}/^{\circ}\text{C}$ (max)
- Safety-Related Certifications:
 - 7000- V_{PK} Reinforced Isolation per DIN V VDE V 0884-10 (VDE V 0884-10): 2006-12
 - 5000- V_{RMS} Isolation for 1 Minute per UL1577
 - CAN/CSA No. 5A-Component Acceptance Service Notice
- Transient Immunity: $15\ \text{kV}/\mu\text{s}$ (min)
- High Electromagnetic Field Immunity (see Application Note [SLLA181A](#))
- External 5-MHz to 20-MHz Clock Input

2 Applications

- Shunt-Based Current Sensing or Resistor-Divider-Based Voltage Sensing In:
 - Traction Inverters
 - Onboard Chargers (OBC)
 - DC-DC Converters
 - Battery Management Systems (BMS)

3 Description

The AMC1305-Q1 device is a precision, delta-sigma ($\Delta\Sigma$) modulator with the output separated from the input circuitry by a capacitive double isolation barrier that is highly resistant to magnetic interference. This barrier is certified to provide reinforced isolation of up to $7000\ V_{\text{PEAK}}$ according to the DIN V VDE V 0884-10, UL1577, and CSA standards. Used in conjunction with isolated power supplies, the device prevents noise currents on a high common-mode voltage line from entering the local system ground and interfering with or damaging low voltage circuitry.

The AMC1305-Q1 is optimized for direct connection to shunt resistors or other low voltage level signal sources and supports excellent dc and ac performance. Shunt resistors are typically used to sense currents in traction inverters, onboard chargers, or other such automotive applications. By using an appropriate digital filter (that is, as integrated on the [TMS320F2837x](#)) to decimate the bit stream, the device can achieve 16 bits of resolution with a dynamic range of 85 dB (13.8 ENOB) at a data rate of 78 kSPS.

On the high-side, the modulator is supplied with a nominal voltage of 5 V (AVDD), whereas the isolated digital interface operates from a 3.3-V or 5-V power supply (DVDD).

The AMC1305-Q1 is available in a wide-body SOIC-16 (DW) package.

Device Information⁽¹⁾

| PART NUMBER | PACKAGE | BODY SIZE (NOM) |
|-------------|-----------|--------------------|
| AMC1305x-Q1 | SOIC (16) | 10.30 mm x 7.50 mm |

(1) For all available packages, see the orderable addendum at the end of the datasheet.

Simplified Schematic

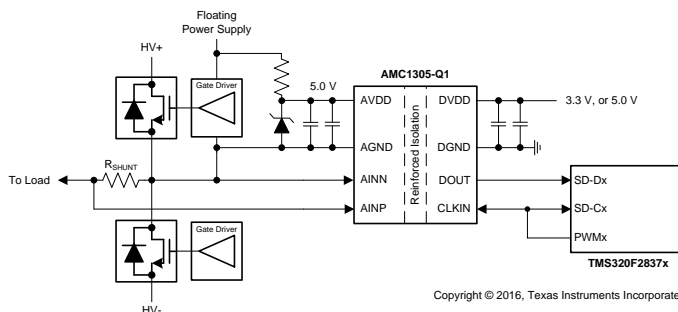


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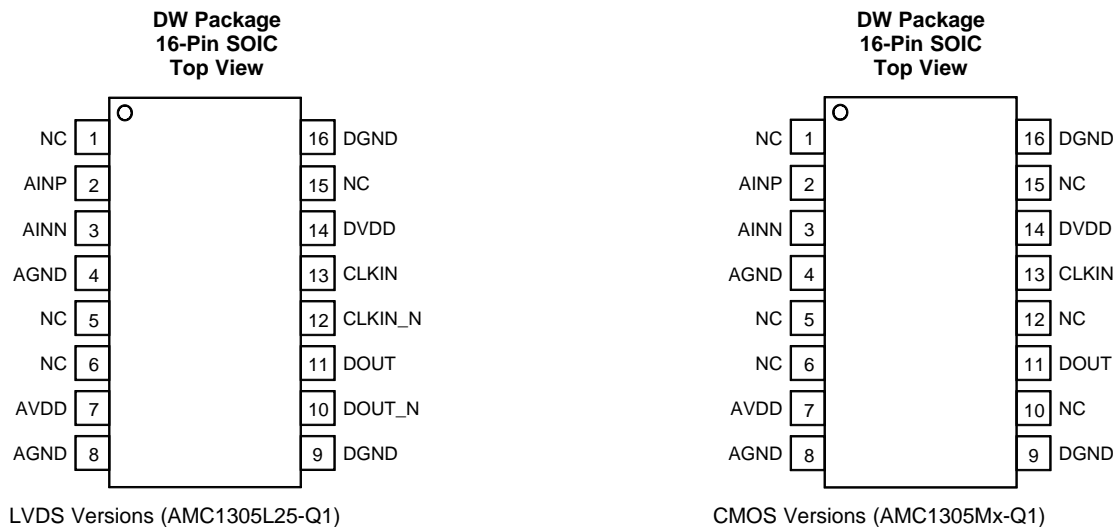
4 Revision History

| DATE | REVISION | NOTES |
|---------------|----------|------------------|
| February 2017 | * | Initial release. |

5 Device Comparison Table

| PART NUMBER | INPUT VOLTAGE RANGE | DIFFERENTIAL INPUT RESISTANCE | SNR (sinc ³ Filter, 78 kSPS) | OUTPUT INTERFACE |
|---------------|---------------------|-------------------------------|---|------------------|
| AMC1305L25-Q1 | ±250 mV | 25 kΩ | 82 dB | LVDS |
| AMC1305M05-Q1 | ±50 mV | 5 kΩ | 76 dB | CMOS |
| AMC1305M25-Q1 | ±250 mV | 25 kΩ | 82 dB | CMOS |

6 Pin Configurations and Functions



Pin Functions

| PIN | | I/O | DESCRIPTION |
|---------|-----------|-----|---|
| NAME | NO. | | |
| AGND | 4 | — | This pin is internally connected to pin 8 and can be left unconnected or tied to high-side ground |
| | 8 | — | High-side ground reference |
| AINN | 3 | I | Inverting analog input |
| AINP | 2 | I | Noninverting analog input |
| AVDD | 7 | — | High-side power supply, 4.5 V to 5.5 V. See the Power-Supply Recommendations section for decoupling recommendations. |
| CLKIN | 13 | I | Modulator clock input, 5 MHz to 20.1 MHz |
| CLKIN_N | 12 | I | AMC1305L25-Q1 only: inverted modulator clock input |
| DGND | 9, 16 | — | Controller-side ground reference |
| DOUT | 11 | O | Modulator data output |
| DOUT_N | 10 | O | AMC1305L25-Q1 only: inverted modulator data output |
| DVDD | 14 | — | Controller-side power supply, 3.0 to 5.5 V |
| NC | 1 | — | This pin can be connected to AVDD or can be left unconnected |
| | 5 | — | This pin can be left unconnected or tied to AGND only |
| | 6, 10, 12 | — | These pins have no internal connection (pins 10 and 12 on the AMC1305Mx-Q1 only). |
| | 15 | — | This pin can be left unconnected or tied to DVDD only |

7 Specifications

7.1 Absolute Maximum Ratings

over the operating ambient temperature range (unless otherwise noted)⁽¹⁾

| | MIN | MAX | UNIT |
|--|------------|------------|------|
| Supply voltage, AVDD to AGND or DVDD to DGND | -0.3 | 6.5 | V |
| Analog input voltage at AINP, AINN | AGND – 6 | AVDD + 0.5 | V |
| Digital input voltage at CLKIN, CLKIN_N | DGND – 0.3 | DVDD + 0.3 | V |
| Input current to any pin except supply pins | -10 | 10 | mA |
| Maximum virtual junction temperature, T _J | | 150 | °C |
| Storage temperature, T _{stg} | -65 | 150 | °C |

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and do not imply functional operation of the device at these or any other conditions beyond those indicated. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

7.2 ESD Ratings

| | | VALUE | UNIT |
|--------------------|-------------------------|---|-------|
| V _(ESD) | Electrostatic discharge | Human body model (HBM), per AEC Q100-002 ⁽¹⁾ | ±2500 |
| | | Charged device model (CDM), per AEC Q100-011 | ±1000 |

(1) AEC Q100-002 indicates HBM stressing is done in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

| | | MIN | NOM | MAX | UNIT |
|----------------|--|-----|-----|-----|------|
| AVDD | High-side (analog) supply voltage | 4.5 | 5.0 | 5.5 | V |
| DVDD | Controller-side (digital) supply voltage | 3.0 | 3.3 | 5.5 | V |
| T _A | Operating ambient temperature range | -40 | | 125 | °C |

7.4 Thermal Information

| THERMAL METRIC ⁽¹⁾ | | AMC1305x-Q1 | UNIT |
|-------------------------------|--|-------------|------|
| | | DW (SOIC) | |
| | | 16 PINS | |
| R _{θJA} | Junction-to-ambient thermal resistance | 80.2 | °C/W |
| R _{θJC(top)} | Junction-to-case (top) thermal resistance | 40.5 | °C/W |
| R _{θJB} | Junction-to-board thermal resistance | 45.1 | °C/W |
| ψ _{JT} | Junction-to-top characterization parameter | 11.9 | °C/W |
| ψ _{JB} | Junction-to-board characterization parameter | 44.5 | °C/W |
| R _{θJC(bot)} | Junction-to-case (bottom) thermal resistance | n/a | °C/W |

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

7.5 Power Ratings

| PARAMETER | TEST CONDITIONS | VALUE | UNIT |
|-----------------|--|---|------|
| P _D | Maximum power dissipation (both sides) | AVDD = 5.5 V, DVDD = 5.5 V, LVDS, R _{LOAD} = 100 Ω | 89.1 |
| P _{D1} | Maximum power dissipation (high-side supply) | AVDD = 5.5 V | 45.1 |
| P _{D2} | Maximum power dissipation (low-side supply) | DVDD = 5.5 V, LVDS, R _{LOAD} = 100 Ω | 44 |

7.6 Insulation Specifications

| PARAMETER | | TEST CONDITIONS | VALUE | UNIT |
|---|---|---|-------------------|------------------|
| GENERAL | | | | |
| CLR | Minimum air gap (clearance) ⁽¹⁾ | Shortest pin-to-pin distance through air | ≥ 8 | mm |
| CPG | Minimum external tracking (creepage) ⁽¹⁾ | Shortest pin-to-pin distance across the package surface | ≥ 8 | mm |
| DTI | Distance through insulation | Minimum internal gap (internal clearance) of the double insulation (2 × 0.0135 mm) | 0.027 | mm |
| CTI | Comparative tracking index | DIN EN 60112 (VDE 0303-11); IEC 60112 | ≥ 600 | V |
| | Material group | According to IEC 60664-1 | I | |
| | Overvoltage category per IEC 60664-1 | Rated mains voltage ≤ 300 V _{RMS} | I-IV | |
| | | Rated mains voltage ≤ 600 V _{RMS} | I-III | |
| | | Rated mains voltage ≤ 1000 V _{RMS} | I-II | |
| DIN V VDE V 0884-10 (VDE V 0884-10): 2006-12⁽²⁾ | | | | |
| V _{IORM} | Maximum repetitive peak isolation voltage | At ac voltage (bipolar or unipolar) | 1414 | V _{PK} |
| V _{IOWM} | Maximum-rated isolation working voltage | At ac voltage (sine wave) | 1000 | V _{RMS} |
| | | At dc voltage | 1500 | V _{DC} |
| V _{IOTM} | Maximum transient isolation voltage | V _{TEST} = V _{IOTM} , t = 60 s (qualification test) | 7000 | V _{PK} |
| | | V _{TEST} = 1.2 × V _{IOTM} , t = 1 s (100% production test) | 8400 | |
| V _{IOSM} | Maximum surge isolation voltage ⁽³⁾ | Test method per IEC 60065, 1.2/50-μs waveform, V _{TEST} = 1.6 × V _{IOSM} = 10000 V _{PK} (qualification) | 6250 | V _{PK} |
| q _{pd} | Apparent charge ⁽⁴⁾ | Method a, after input/output safety test subgroup 2 / 3, V _{ini} = V _{IOTM} , t _{ini} = 60 s, V _{pd(m)} = 1.2 × V _{IORM} = 1697 V _{PK} , t _m = 10 s | ≤ 5 | pC |
| | | Method a, after environmental tests subgroup 1, V _{ini} = V _{IOTM} , t _{ini} = 60 s, V _{pd(m)} = 1.6 × V _{IORM} = 2263 V _{PK} , t _m = 10 s | ≤ 5 | pC |
| | | Method b1, at routine test (100% production) and preconditioning (type test), V _{ini} = V _{IOTM} , t _{ini} = 1 s, V _{pd(m)} = 1.875 × V _{IORM} = 2652 V _{PK} , t _m = 1 s | ≤ 5 | pC |
| C _{IO} | Barrier capacitance, input to output ⁽⁵⁾ | V _{IO} = 0.5 V _{PP} at 1 MHz | 1.2 | pF |
| R _{IO} | Insulation resistance, input to output ⁽⁵⁾ | V _{IO} = 500 V at T _S = 150°C | > 10 ⁹ | Ω |
| | Pollution degree | | 2 | |
| | Climatic category | | 40/125/21 | |
| UL1577 | | | | |
| V _{ISO} | Withstand isolation voltage | V _{TEST} = V _{ISO} = 5000 V _{RMS} or 7000 V _{DC} , t = 60 s (qualification test), V _{TEST} = 1.2 × V _{ISO} = 6000 V _{RMS} , t = 1 s (100% production test) | 5000 | V _{RMS} |

- (1) Apply creepage and clearance requirements according to the specific equipment isolation standards of an application. Care must be taken to maintain the creepage and clearance distance of a board design to ensure that the mounting pads of the isolator on the printed circuit board (PCB) do not reduce this distance. Creepage and clearance on a PCB become equal in certain cases. Techniques such as inserting grooves or ribs on the PCB are used to help increase these specifications.
- (2) This coupler is suitable for *safe electrical insulation* only within the safety ratings. Compliance with the safety ratings shall be ensured by means of suitable protective circuits.
- (3) Testing is carried out in air or oil to determine the intrinsic surge immunity of the isolation barrier.
- (4) Apparent charge is electrical discharge caused by a partial discharge (pd).
- (5) All pins on each side of the barrier are tied together, creating a two-pin device.

7.7 Safety-Related Certifications

| VDE | UL |
|--|--|
| Certified according to DIN V VDE V 0884-10 (VDE V 0884-10): 2006-12, DIN EN 60950-1 (VDE 0805 Teil 1): 2014-08, and DIN EN 60095 (VDE 0860): 2005-11 | Recognized under UL1577 component recognition and CSA component acceptance NO 5 programs |
| Reinforced insulation | Single protection |
| File number: 40040142 | File number: E181974 |

7.8 Safety Limiting Values

Safety limiting intends to prevent potential damage to the isolation barrier upon failure of input or output (I/O) circuitry. A failure of the I/O circuitry may allow low resistance to ground or the supply and, without current limiting, dissipate sufficient power to overheat the die and damage the isolation barrier, potentially leading to secondary system failures.

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|--|---|-----|-----|---------------------|------|
| I _S Safety input, output, or supply current | $\theta_{JA} = 80.2^{\circ}\text{C/W}$, AVDD = DVDD = 5.5 V, T _J = 150°C, T _A = 25°C, see Figure 3 | | | 283 | mA |
| | $\theta_{JA} = 80.2^{\circ}\text{C/W}$, AVDD = DVDD = 3.6 V, T _J = 150°C, T _A = 25°C, see Figure 3 | | | 432 | mA |
| P _S Safety input, output, or total power | $\theta_{JA} = 80.2^{\circ}\text{C/W}$, T _J = 150°C, T _A = 25°C, see Figure 4 | | | 1558 ⁽¹⁾ | mW |
| T _S Maximum safety temperature | | | | 150 | °C |

(1) Input, output, or the sum of input and output power must not exceed this value.

The maximum safety temperature is the maximum junction temperature specified for the device. The power dissipation and junction-to-air thermal impedance of the device installed in the application hardware determines the junction temperature. The assumed junction-to-air thermal resistance in the [Thermal Information](#) table is that of a device installed on a high-K test board for leaded surface-mount packages. The power is the recommended maximum input voltage times the current. The junction temperature is then the ambient temperature plus the power times the junction-to-air thermal resistance.

7.9 Electrical Characteristics: AMC1305M05-Q1

All minimum and maximum specifications at $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$, $AVDD = 4.5\text{ V}$ to 5.5 V , $DVDD = 3.0\text{ V}$ to 5.5 V , $AINP = -50\text{ mV}$ to 50 mV , $AINN = 0\text{ V}$, and sinc³ filter with OSR = 256, unless otherwise noted. Typical values are at $T_A = 25^\circ\text{C}$, $CLKIN = 20\text{ MHz}$, $AVDD = 5.0\text{ V}$, and $DVDD = 3.3\text{ V}$.

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|---|--|---|-------------------|--------|-------------------|--------|
| ANALOG INPUTS | | | | | | |
| V_{Clipping} | Maximum differential voltage input range (AINP-AINN) | | | ±62.5 | | mV |
| FSR | Specified linear full-scale range (AINP-AINN) | | -50 | | 50 | mV |
| V_{CM} | Operating common-mode input range | | -0.032 | | $AVDD - 2$ | V |
| C_{ID} | Differential input capacitance | | | 2 | | pF |
| I_{IB} | Input current | Inputs shorted to AGND | -97 | -72 | -57 | µA |
| R_{ID} | Differential input resistance | | | 5 | | kΩ |
| I_{OS} | Input offset current | | | ±5 | | nA |
| CMTI | Common-mode transient immunity | | 15 | | | kV/µs |
| CMRR | Common-mode rejection ratio | $f_{\text{IN}} = 0\text{ Hz}$, $V_{\text{CM min}} \leq V_{\text{IN}} \leq V_{\text{CM max}}$ | | -104 | | dB |
| | | f_{IN} from 0.1 Hz to 50 kHz, $V_{\text{CM min}} \leq V_{\text{IN}} \leq V_{\text{CM max}}$ | | -75 | | |
| BW | Input bandwidth | | | 800 | | kHz |
| DC ACCURACY | | | | | | |
| DNL | Differential nonlinearity | Resolution: 16 bits | -0.99 | | 0.99 | LSB |
| INL | Integral nonlinearity ⁽¹⁾ | Resolution: 16 bits | -5 | ±1.5 | 5 | LSB |
| E_{O} | Offset error | Initial, at 25°C | -50 | ±2.5 | 50 | µV |
| TCE_{O} | Offset error thermal drift ⁽²⁾ | | -1.3 | | 1.3 | µV/°C |
| E_{G} | Gain error | Initial, at 25°C | -0.3% | -0.02% | 0.3% | |
| TCE_{G} | Gain error thermal drift ⁽³⁾ | | -40 | ±20 | 40 | ppm/°C |
| PSRR | Power-supply rejection ratio | V_{AVDD} from 4.5 to 5.5V, at dc | | 105 | | dB |
| AC ACCURACY | | | | | | |
| SNR | Signal-to-noise ratio | $f_{\text{IN}} = 1\text{ kHz}$ | 76 | 81 | | dB |
| SINAD | Signal-to-noise + distortion | $f_{\text{IN}} = 1\text{ kHz}$ | 76 | 81 | | dB |
| THD | Total harmonic distortion | $f_{\text{IN}} = 1\text{ kHz}$ | | -90 | -83 | dB |
| SFDR | Spurious-free dynamic range | $f_{\text{IN}} = 1\text{ kHz}$ | 83 | 92 | | dB |
| DIGITAL INPUTS/OUTPUTS | | | | | | |
| External Clock | | | | | | |
| f_{CLKIN} | Input clock frequency | | 5 | 20 | 20.1 | MHz |
| Duty _{CLKIN} | Duty cycle | $5\text{ MHz} \leq f_{\text{CLKIN}} \leq 20.1\text{ MHz}$ | 40% | 50% | 60% | |
| CMOS Logic Family, CMOS with Schmitt-Trigger | | | | | | |
| I_{IN} | Input current | $DGND \leq V_{\text{IN}} \leq DVDD$ | -1 | | 1 | µA |
| C_{IN} | Input capacitance | | | 5 | | pF |
| V_{IH} | High-level input voltage | | $0.7 \times DVDD$ | | $DVDD + 0.3$ | V |
| V_{IL} | Low-level input voltage | | -0.3 | | $0.3 \times DVDD$ | V |
| C_{LOAD} | Output load capacitance | $f_{\text{CLKIN}} = 20\text{ MHz}$ | | 30 | | pF |
| V_{OH} | High-level output voltage | $I_{\text{OH}} = -20\text{ µA}$ | $DVDD - 0.1$ | | | V |
| | | $I_{\text{OH}} = -4\text{ mA}$ | $DVDD - 0.4$ | | | |
| V_{OL} | Low-level output voltage | $I_{\text{OL}} = 20\text{ µA}$ | | | 0.1 | V |
| | | $I_{\text{OL}} = 4\text{ mA}$ | | | 0.4 | |

(1) Integral nonlinearity is defined as the maximum deviation from a straight line passing through the end-points of the ideal ADC transfer function expressed as number of LSBs or as a percent of the specified linear full-scale range FSR.

(2) Offset error drift is calculated using the box method as described by the following equation:

$$TCE_{\text{O}} = \frac{\text{value}_{\text{MAX}} - \text{value}_{\text{MIN}}}{\text{TempRange}}$$

(3) Gain error drift is calculated using the box method as described by the following equation:

$$TCE_{\text{G}} (\text{ppm}) = \left(\frac{\text{value}_{\text{MAX}} - \text{value}_{\text{MIN}}}{\text{value} \times \text{TempRange}} \right) \times 10^6$$

Electrical Characteristics: AMC1305M05-Q1 (continued)

All minimum and maximum specifications at $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$, $AVDD = 4.5\text{ V}$ to 5.5 V , $DVDD = 3.0\text{ V}$ to 5.5 V , $A\text{INP} = -50\text{ mV}$ to 50 mV , $A\text{INN} = 0\text{ V}$, and sinc³ filter with $\text{OSR} = 256$, unless otherwise noted. Typical values are at $T_A = 25^\circ\text{C}$, $\text{CLKIN} = 20\text{ MHz}$, $AVDD = 5.0\text{ V}$, and $DVDD = 3.3\text{ V}$.

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|---------------------|-----------------------------------|----------------------|-----|------|------|------|
| POWER SUPPLY | | | | | | |
| AVDD | High-side supply voltage | | 4.5 | 5.0 | 5.5 | V |
| I _{AVDD} | High-side supply current | | | 6.5 | 8.2 | mA |
| P _{AVDD} | High-side power dissipation | | | 32.5 | 45.1 | mW |
| DVDD | Controller-side supply voltage | | 3.0 | 3.3 | 5.5 | V |
| I _{DVDD} | Controller-side supply current | 3.0 V ≤ DVDD ≤ 3.6 V | | 2.7 | 4.0 | mA |
| | | 4.5 V ≤ DVDD ≤ 5.5 V | | 3.2 | 5.5 | |
| P _{DVDD} | Controller-side power dissipation | 3.0 V ≤ DVDD ≤ 3.6 V | | 8.9 | 14.4 | mW |
| | | 4.5 V ≤ DVDD ≤ 5.5 V | | 16.0 | 30.3 | |

7.10 Electrical Characteristics: AMC1305x25-Q1

All minimum and maximum specifications at $T_A = -40^\circ\text{C}$ to 125°C , $AVDD = 4.5\text{ V}$ to 5.5 V , $DVDD = 3.0\text{ V}$ to 5.5 V , $AINP = -250\text{ mV}$ to 250 mV , $AINN = 0\text{ V}$, and sinc³ filter with $OSR = 256$, unless otherwise noted. Typical values are at $T_A = 25^\circ\text{C}$, $CLKIN = 20\text{ MHz}$, $AVDD = 5.0\text{ V}$, and $DVDD = 3.3\text{ V}$.

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|---|--|---|-------------------|-------------|-------------------|------------------------------|
| ANALOG INPUTS | | | | | | |
| $V_{Clipping}$ | Maximum differential voltage input range (AINP-AINN) | | | ± 312.5 | | mV |
| FSR | Specified linear full-scale range (AINP-AINN) | | -250 | | 250 | mV |
| V_{CM} | Operating common-mode input range | | -0.16 | | $AVDD - 2$ | V |
| C_{ID} | Differential input capacitance | | | 1 | | pF |
| I_{IB} | Input current | Inputs shorted to AGND | -82 | -60 | -48 | μA |
| R_{ID} | Differential input resistance | | | 25 | | k Ω |
| I_{OS} | Input offset current | | | ± 5 | | nA |
| CMTI | Common-mode transient immunity | | 15 | | | kV/ μs |
| CMRR | Common-mode rejection ratio | $f_{IN} = 0\text{ Hz}$, $V_{CM\ min} \leq V_{IN} \leq V_{CM\ max}$ | | -95 | | dB |
| | | f_{IN} from 0.1 Hz to 50 kHz, $V_{CM\ min} \leq V_{IN} \leq V_{CM\ max}$ | | -76 | | |
| BW | Input bandwidth | | | 1000 | | kHz |
| DC ACCURACY | | | | | | |
| DNL | Differential nonlinearity | Resolution: 16 bits | -0.99 | | 0.99 | LSB |
| INL | Integral nonlinearity ⁽¹⁾ | Resolution: 16 bits | -4 | ± 1.5 | 4 | LSB |
| E_O | Offset error | Initial, at 25°C | -150 | ± 40 | 150 | μV |
| TCE_O | Offset error thermal drift ⁽²⁾ | | -1.3 | | 1.3 | $\mu\text{V}/^\circ\text{C}$ |
| E_G | Gain error | Initial, at 25°C | -0.3 | -0.02 | 0.3 | %FS |
| TCE_G | Gain error thermal drift ⁽³⁾ | | -40 | ± 20 | 40 | ppm/ $^\circ\text{C}$ |
| PSRR | Power-supply rejection ratio | V_{AVDD} from 4.5 V to 5.5 V, at dc | | 90 | | dB |
| AC ACCURACY | | | | | | |
| SNR | Signal-to-noise ratio | $f_{IN} = 1\text{ kHz}$ | 82 | 85 | | dB |
| SINAD | Signal-to-noise + distortion | $f_{IN} = 1\text{ kHz}$ | 80 | 84 | | dB |
| THD | Total harmonic distortion | $f_{IN} = 1\text{ kHz}$ | | -90 | -83 | dB |
| SFDR | Spurious-free dynamic range | $f_{IN} = 1\text{ kHz}$ | 83 | 92 | | dB |
| DIGITAL INPUTS/OUTPUTS | | | | | | |
| External Clock | | | | | | |
| f_{CLKIN} | Input clock frequency | | 5 | 20 | 20.1 | MHz |
| Duty _{CLKIN} | Duty cycle | $5\text{ MHz} \leq f_{CLKIN} \leq 20.1\text{ MHz}$ | 40% | 50% | 60% | |
| CMOS Logic Family (AMC1305M25-Q1), CMOS with Schmitt-Trigger | | | | | | |
| I_{IN} | Input current | $DGND \leq V_{IN} \leq DVDD$ | -1 | | 1 | μA |
| C_{IN} | Input capacitance | | | 5 | | pF |
| V_{IH} | High-level input voltage | | $0.7 \times DVDD$ | | $DVDD + 0.3$ | V |
| V_{IL} | Low-level input voltage | | -0.3 | | $0.3 \times DVDD$ | V |
| C_{LOAD} | Output load capacitance | $f_{CLKIN} = 20\text{ MHz}$ | | 30 | | pF |
| V_{OH} | High-level output voltage | $I_{OH} = -20\ \mu\text{A}$ | $DVDD - 0.1$ | | | V |
| | | $I_{OH} = -4\ \text{mA}$ | $DVDD - 0.4$ | | | |
| V_{OL} | Low-level output voltage | $I_{OL} = 20\ \mu\text{A}$ | | | 0.1 | V |
| | | $I_{OL} = 4\ \text{mA}$ | | | 0.4 | |

(1) Integral nonlinearity is defined as the maximum deviation from a straight line passing through the end-points of the ideal ADC transfer function expressed as the number of LSBs or as a percent of the specified linear full-scale range FSR.

(2) Offset error drift is calculated using the box method as described by the following equation:

$$TCE_O = \frac{value_{MAX} - value_{MIN}}{TempRange}$$

(3) Gain error drift is calculated using the box method as described by the following equation:

$$TCE_G (ppm) = \left(\frac{value_{MAX} - value_{MIN}}{value \times TempRange} \right) \times 10^6$$

Electrical Characteristics: AMC1305x25-Q1 (continued)

All minimum and maximum specifications at $T_A = -40^\circ\text{C}$ to 125°C , $AVDD = 4.5\text{ V}$ to 5.5 V , $DVDD = 3.0\text{ V}$ to 5.5 V , $A_{INP} = -250\text{ mV}$ to 250 mV , $A_{INN} = 0\text{ V}$, and sinc³ filter with $OSR = 256$, unless otherwise noted. Typical values are at $T_A = 25^\circ\text{C}$, $CLKIN = 20\text{ MHz}$, $AVDD = 5.0\text{ V}$, and $DVDD = 3.3\text{ V}$.

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|--|-----------------------------------|---|-------|------|-------|---------------|
| LVDS Logic Family (AMC1305L25-Q1) | | | | | | |
| V_{OD} | Differential output voltage | $R_{LOAD} = 100\ \Omega$ | 250 | 350 | 450 | mV |
| V_{OCM} | Output common-mode voltage | | 1.125 | 1.23 | 1.375 | V |
| I_S | Output short-circuit current | | | | 24 | mA |
| V_{ICM} | Input common-mode voltage | $V_{ID} = 100\text{ mV}$ | 0.05 | 1.25 | 3.25 | V |
| V_{ID} | Differential input voltage | | 100 | 350 | 600 | mV |
| I_{IN} | Input current | $DGND \leq V_{IN} \leq 3.3\text{ V}$ | -24 | 0 | 20 | μA |
| POWER SUPPLY | | | | | | |
| $AVDD$ | High-side supply voltage | | 4.5 | 5.0 | 5.5 | V |
| I_{AVDD} | High-side supply current | | | 6.5 | 8.2 | mA |
| P_{AVDD} | High-side power dissipation | | | 32.5 | 45.1 | mW |
| $DVDD$ | Controller-side supply voltage | | 3.0 | 3.3 | 5.5 | V |
| I_{DVDD} | Controller-side supply current | AMC1305L25-Q1, $R_{LOAD} = 100\ \Omega$ | | 6.1 | 8.0 | mA |
| | | AMC1305M25-Q1, $3.0 \leq DVDD \leq 3.6\text{ V}$, $C_{LOAD} = 5\text{ pF}$ | | 2.7 | 4.0 | |
| | | AMC1305M25-Q1, $4.5 \leq DVDD \leq 5.5\text{ V}$, $C_{LOAD} = 5\text{ pF}$ | | 3.2 | 5.5 | |
| P_{DVDD} | Controller-side power dissipation | AMC1305L25-Q1, $R_{LOAD} = 100\ \Omega$ | | 20.1 | 44.0 | mW |
| | | AMC1305M25-Q1, $3.0 \leq DVDD \leq 3.6\text{ V}$, $C_{LOAD} = 5\text{ pF}$ | | 8.9 | 14.4 | |
| | | AMC1305M25-Q1, $4.5 \leq DVDD \leq 5.5\text{ V}$, $C_{LOAD} = 5\text{ pF}$ | | 16.0 | 30.3 | |

7.11 Switching Characteristics

over operating free-air temperature range (unless otherwise noted)

| PARAMETER | | MIN | TYP | MAX | UNIT |
|--------------|---|-------|-----|-----|--------------|
| t_{CLK} | CLKIN, CLKIN_N clock period | 49.75 | 50 | 200 | ns |
| t_{HIGH} | CLKIN, CLKIN_N clock high time | 19.9 | 25 | 120 | ns |
| t_{LOW} | CLKIN, CLKIN_N clock low time | 19.9 | 25 | 120 | ns |
| t_D | Falling edge of CLKIN, CLKIN_N to DOUT, DOUT_N valid delay, $C_{LOAD} = 5\text{ pF}$ | 0 | | 15 | ns |
| t_{iSTART} | Interface startup time (DVDD at 3.0 V min to DOUT, DOUT_N valid with $AVDD \geq 4.5\text{ V}$) | 32 | | 32 | CLKIN cycles |
| t_{ASTART} | Analog startup time (AVDD step up to 4.5 V with $DVDD \geq 3.0\text{ V}$) | | 1 | | ms |

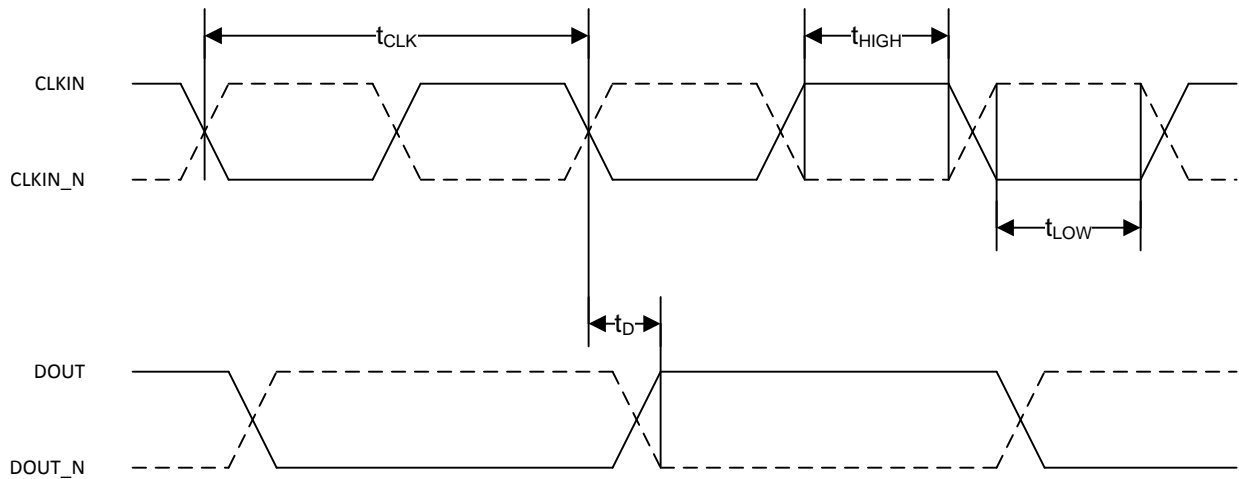


Figure 1. Digital Interface Timing

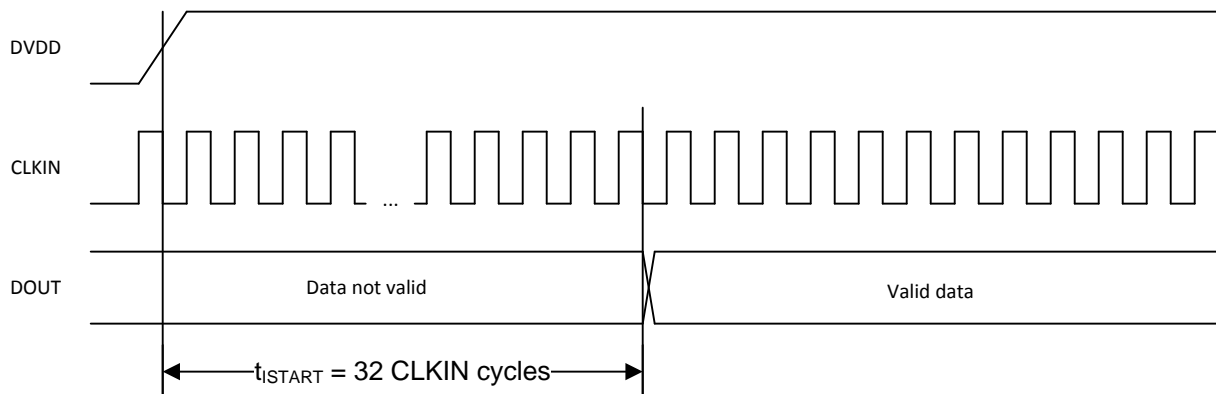
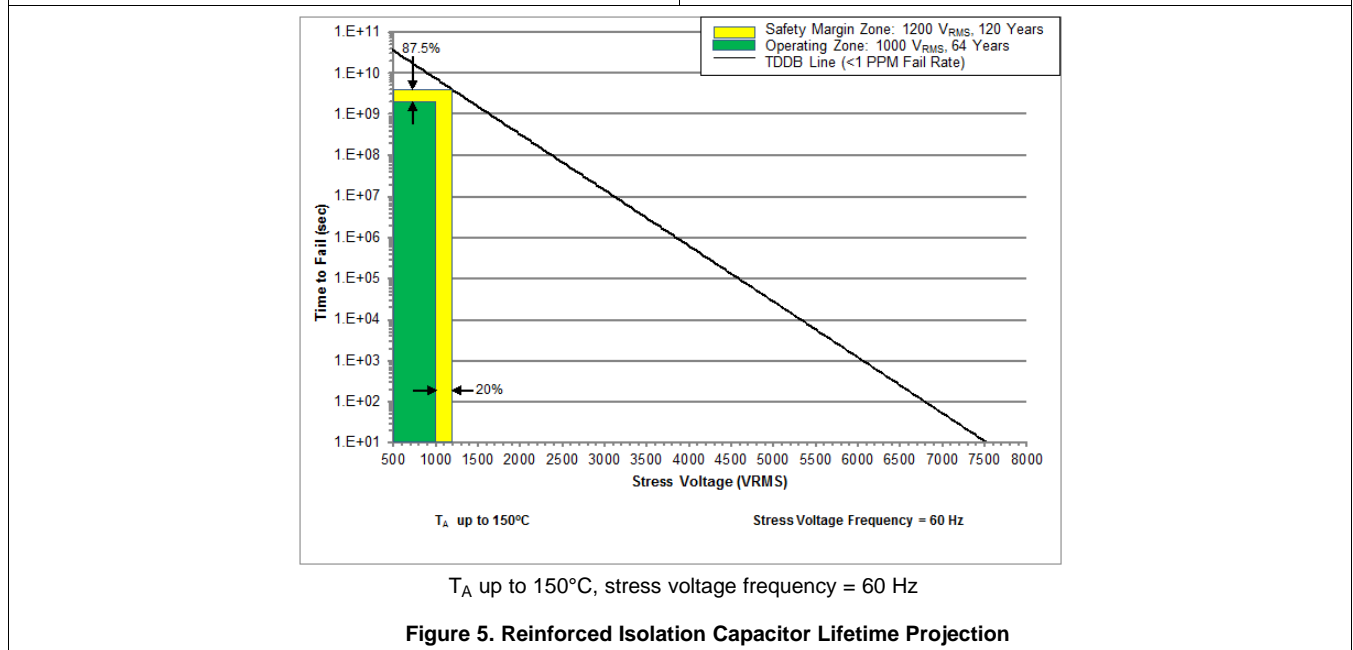
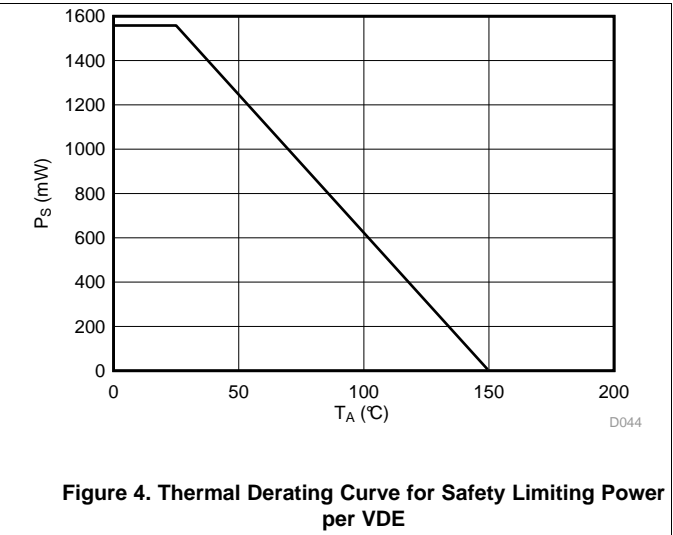
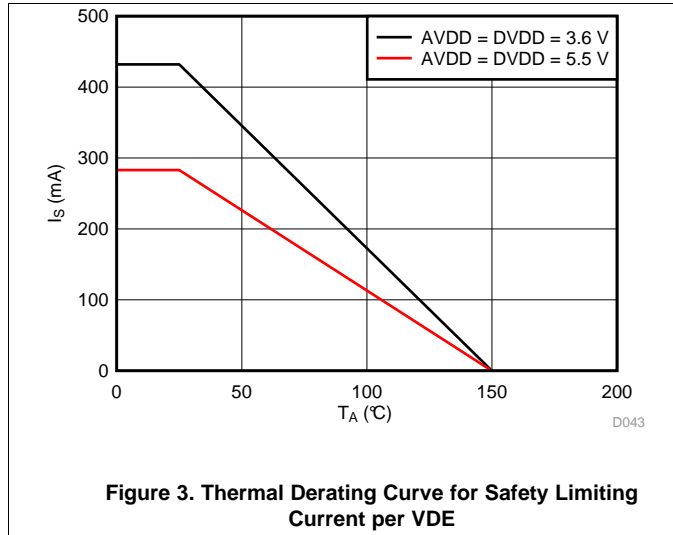


Figure 2. Digital Interface Startup Timing

7.12 Insulation Characteristics Curves



7.13 Typical Characteristics

At $T_A = 25^\circ\text{C}$, $AV_{DD} = 5.0\text{ V}$, $DV_{DD} = 3.3\text{ V}$, $A_{INP} = -250\text{ mV}$ to 250 mV , $A_{INN} = 0\text{ V}$, $f_{CLKIN} = 20\text{ MHz}$, and sinc³ filter with OSR = 256, unless otherwise noted.

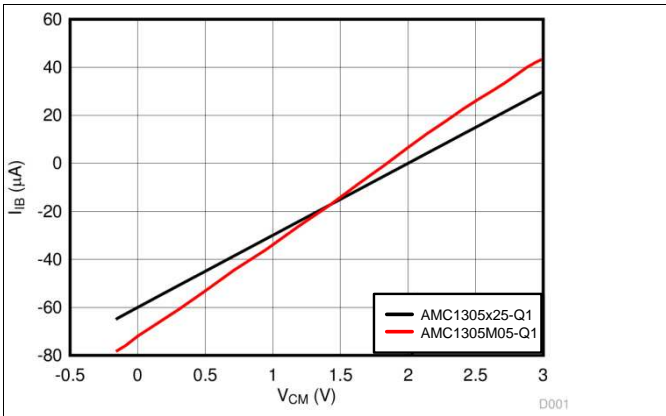


Figure 6. Input Current vs Input Common-Mode Voltage

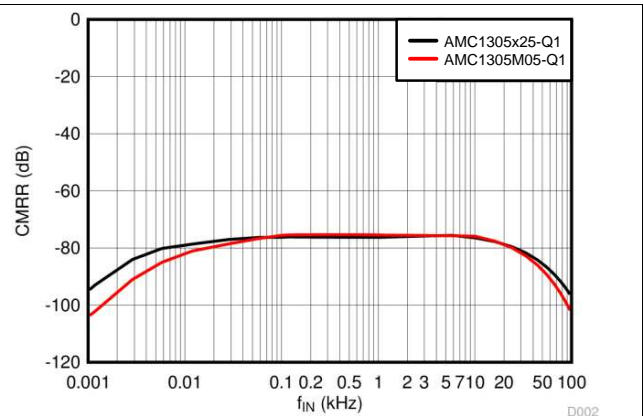


Figure 7. Common-Mode Rejection Ratio vs Input Signal Frequency

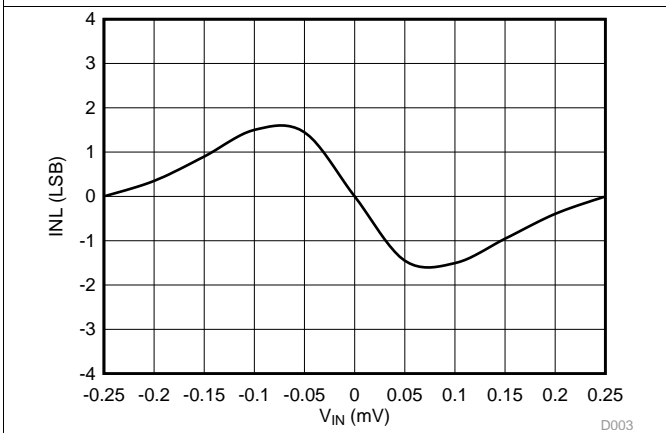


Figure 8. Integral Nonlinearity vs Input Signal Amplitude

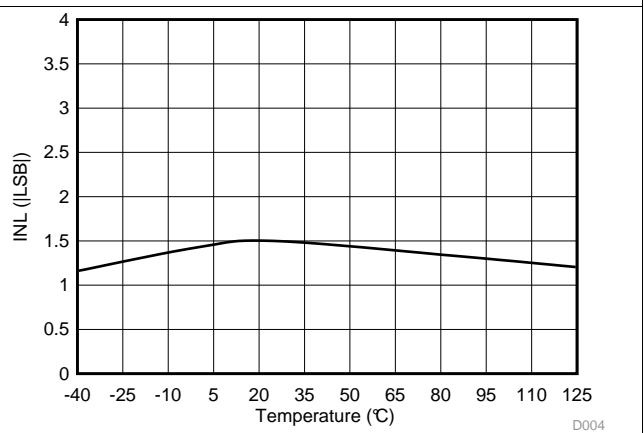


Figure 9. Integral Nonlinearity vs Temperature

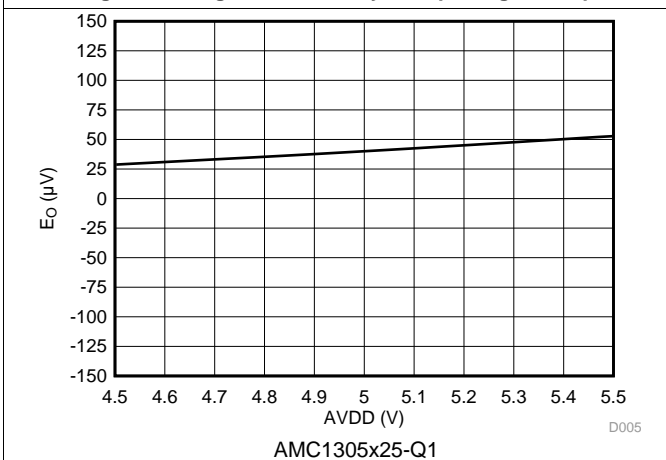


Figure 10. Offset Error vs High-Side Supply Voltage

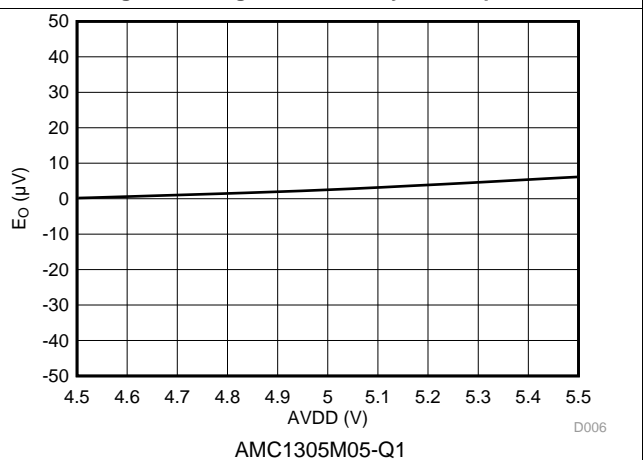


Figure 11. Offset Error vs High-Side Supply Voltage

Typical Characteristics (continued)

At $T_A = 25^\circ\text{C}$, $AV_{DD} = 5.0\text{ V}$, $DV_{DD} = 3.3\text{ V}$, $A_{INP} = -250\text{ mV to } 250\text{ mV}$, $A_{INN} = 0\text{ V}$, $f_{CLKIN} = 20\text{ MHz}$, and sinc³ filter with OSR = 256, unless otherwise noted.

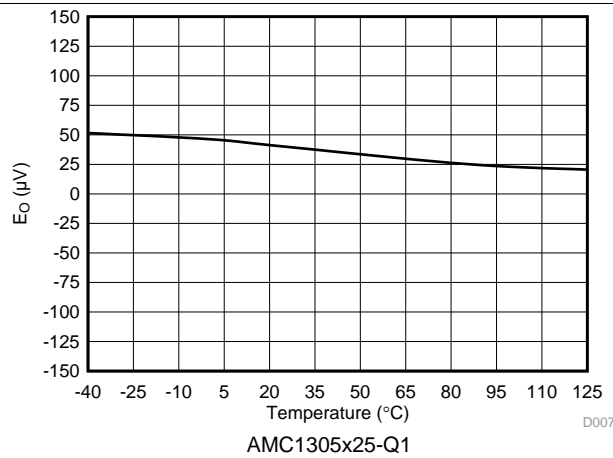


Figure 12. Offset Error vs Temperature

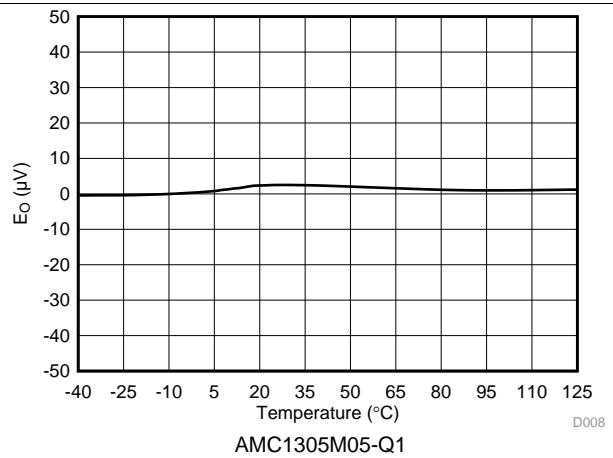


Figure 13. Offset Error vs Temperature

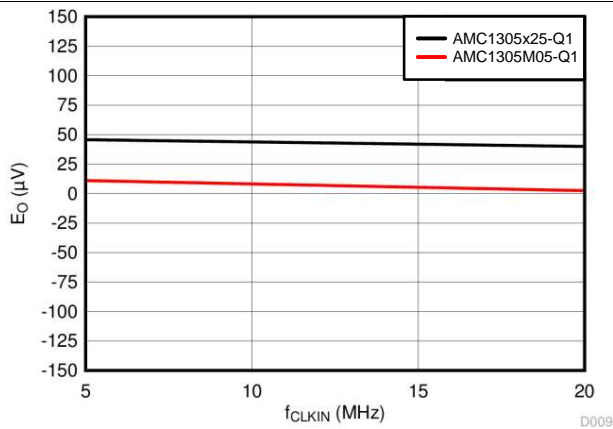


Figure 14. Offset Error vs Clock Frequency

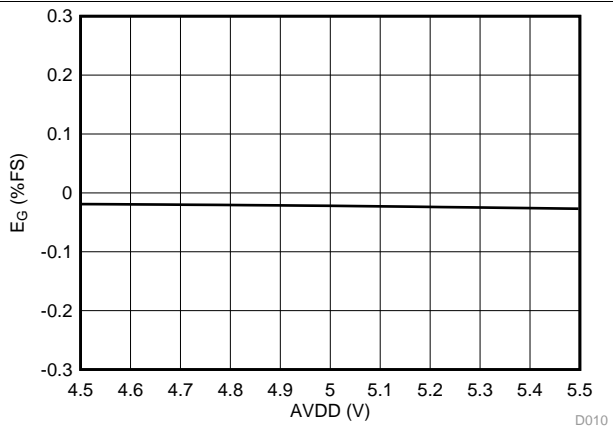


Figure 15. Gain Error vs High-Side Supply Voltage

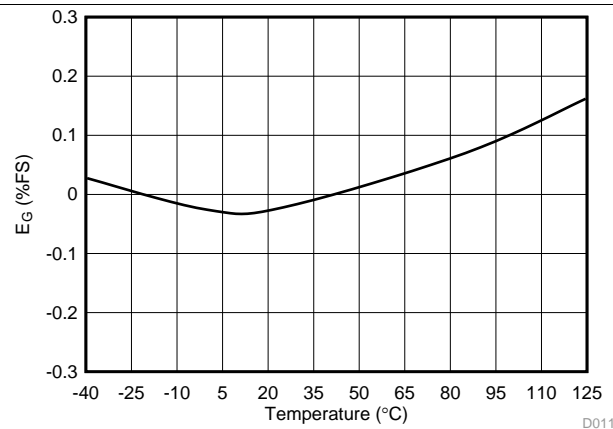


Figure 16. Gain Error vs Temperature

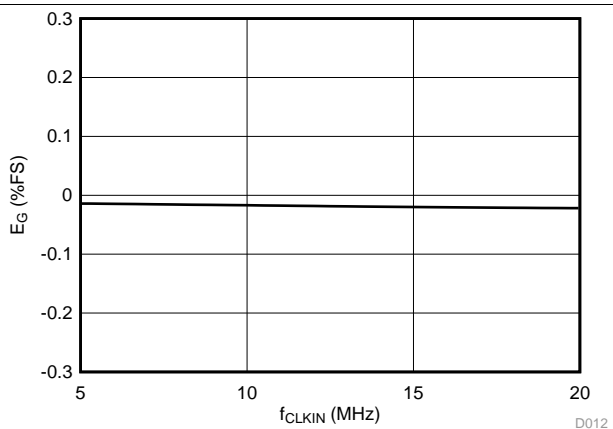


Figure 17. Gain Error vs Clock Frequency

Typical Characteristics (continued)

At $T_A = 25^\circ\text{C}$, $AVDD = 5.0\text{ V}$, $DVDD = 3.3\text{ V}$, $A\text{INP} = -250\text{ mV to }250\text{ mV}$, $A\text{INN} = 0\text{ V}$, $f_{\text{CLKIN}} = 20\text{ MHz}$, and sinc³ filter with OSR = 256, unless otherwise noted.

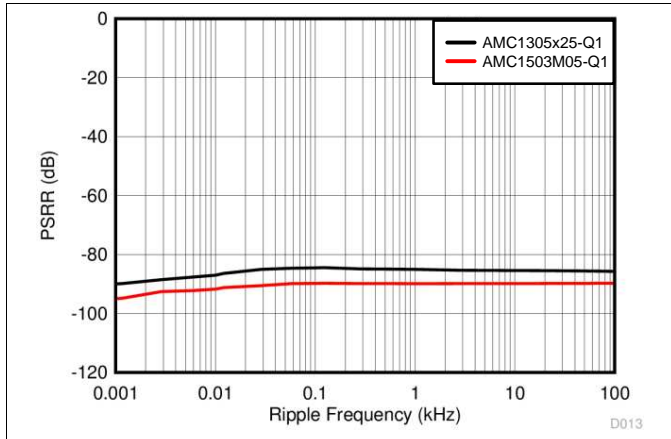


Figure 18. Power-Supply Rejection Ratio vs Ripple Frequency

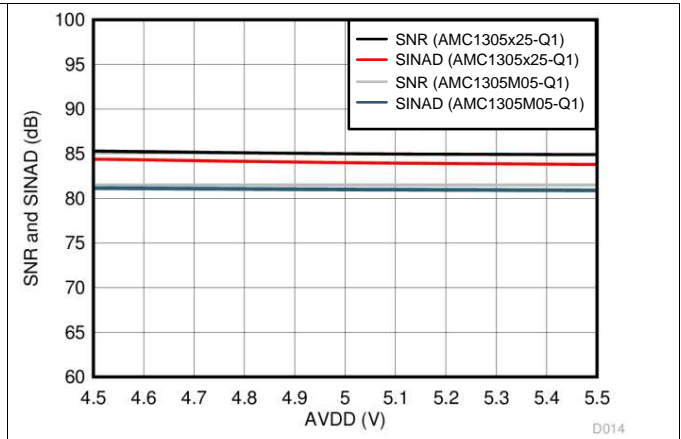


Figure 19. SNR and SINAD vs High-Side Supply Voltage

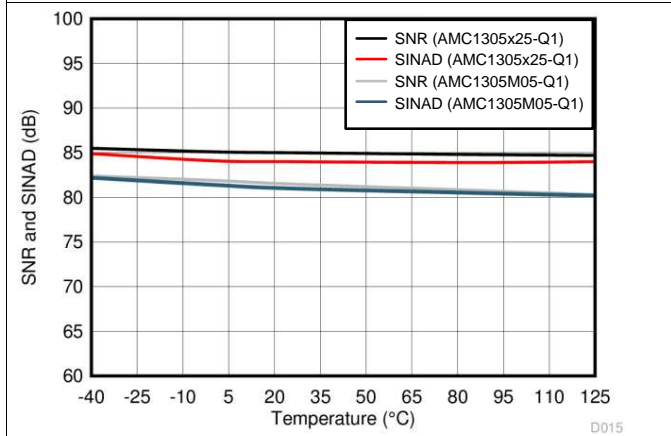


Figure 20. SNR and SINAD vs Temperature

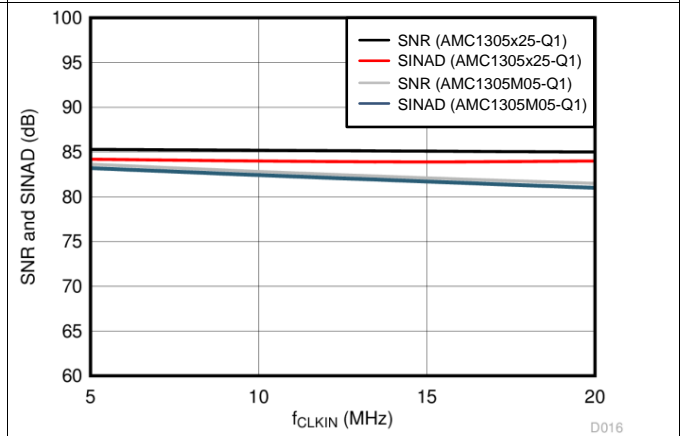


Figure 21. SNR and SINAD vs Clock Frequency

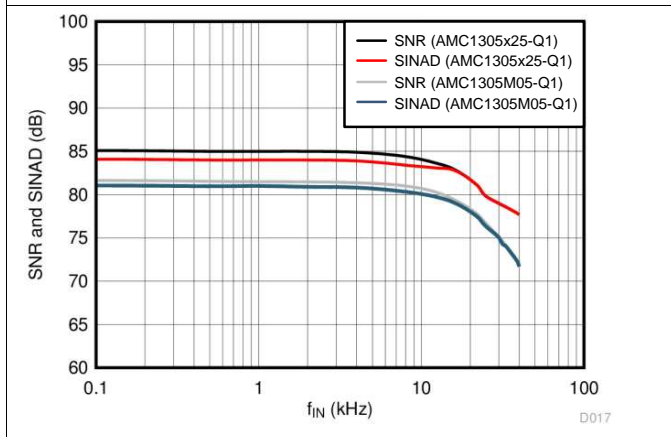


Figure 22. SNR and SINAD vs Input Signal Frequency

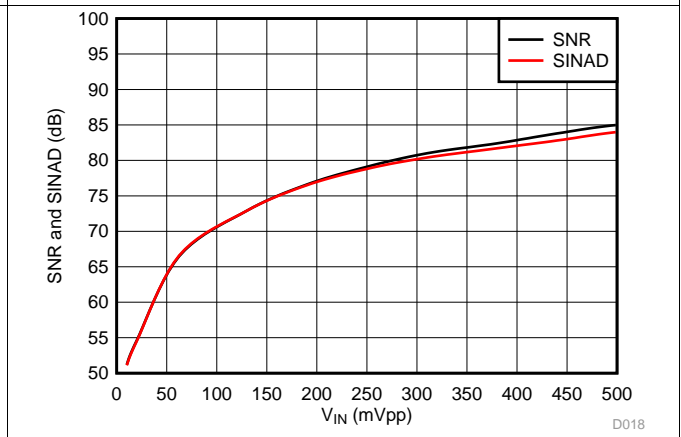
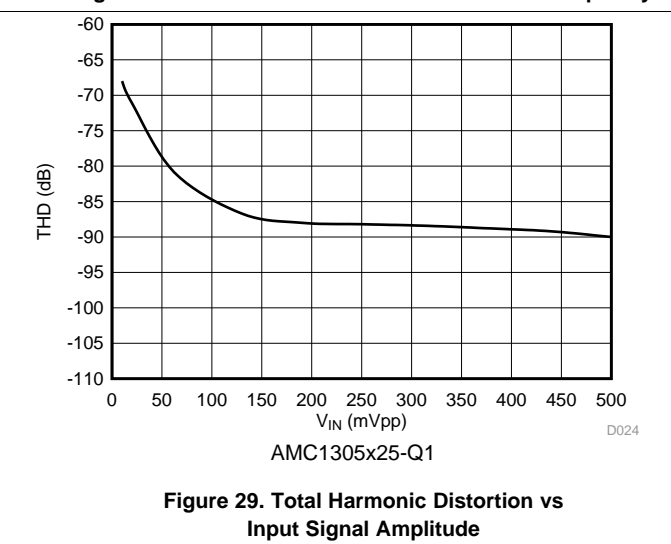
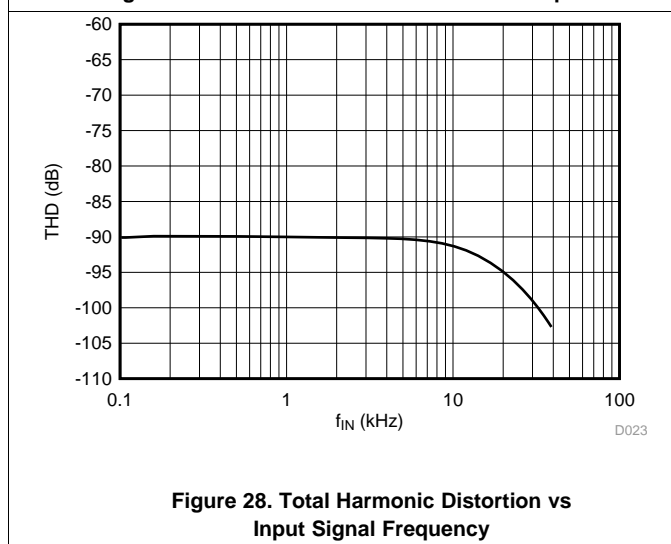
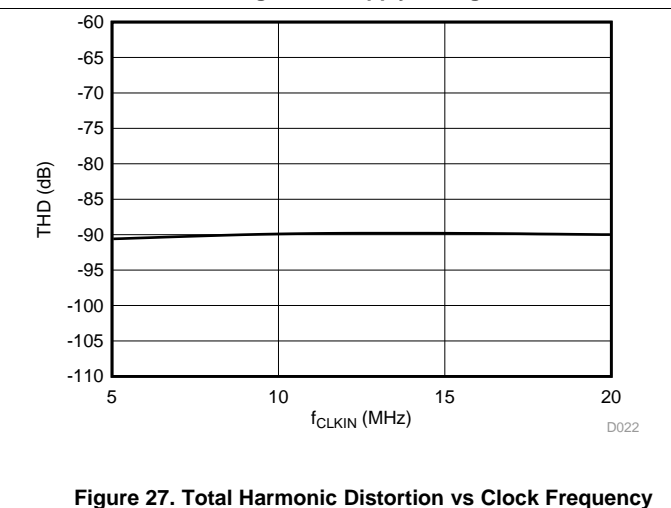
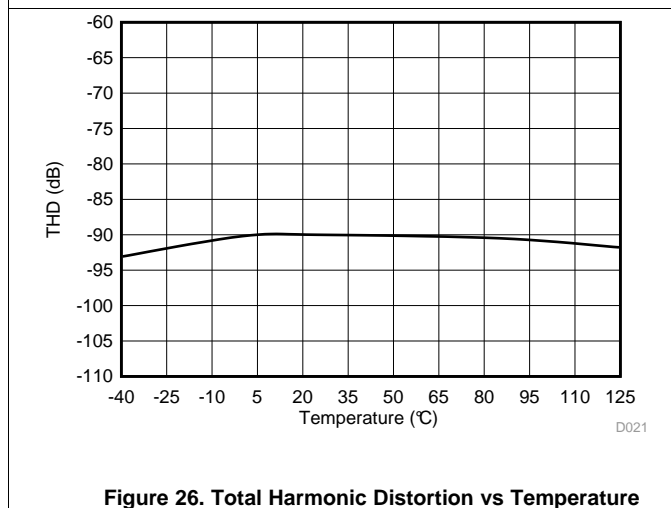
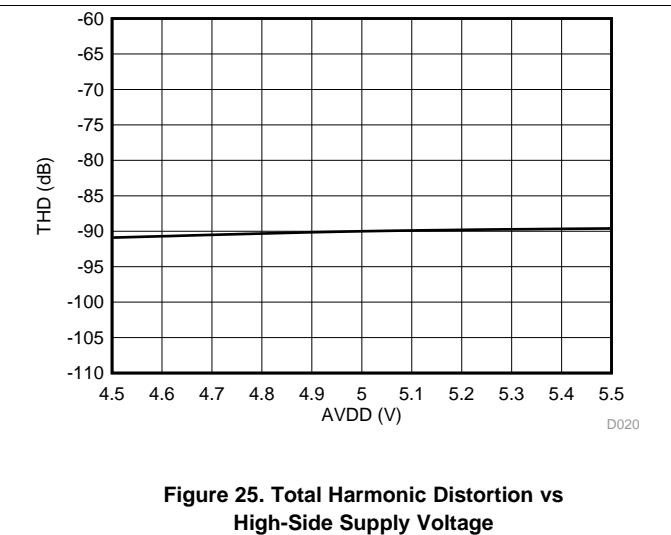
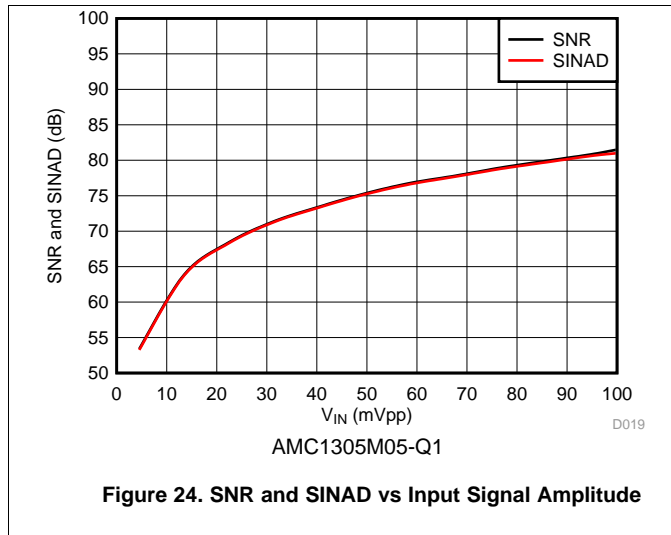


Figure 23. SNR and SINAD vs Input Signal Amplitude

Typical Characteristics (continued)

At $T_A = 25^\circ\text{C}$, $AV_{DD} = 5.0\text{ V}$, $DV_{DD} = 3.3\text{ V}$, $A_{INP} = -250\text{ mV to } 250\text{ mV}$, $A_{INN} = 0\text{ V}$, $f_{CLKIN} = 20\text{ MHz}$, and sinc³ filter with OSR = 256, unless otherwise noted.



Typical Characteristics (continued)

At $T_A = 25^\circ\text{C}$, $AV_{DD} = 5.0\text{ V}$, $DV_{DD} = 3.3\text{ V}$, $A_{INP} = -250\text{ mV to }250\text{ mV}$, $A_{INN} = 0\text{ V}$, $f_{CLKIN} = 20\text{ MHz}$, and sinc³ filter with OSR = 256, unless otherwise noted.

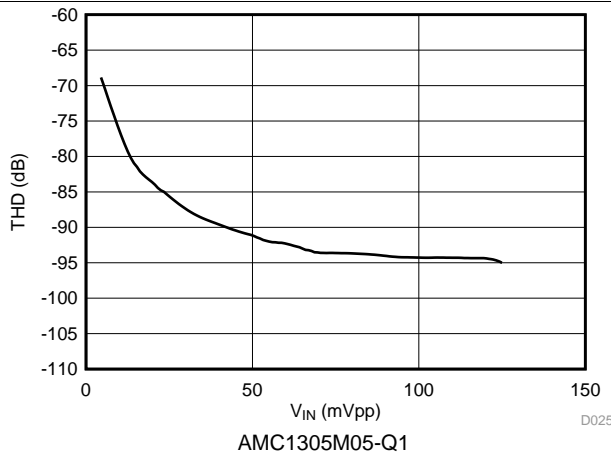


Figure 30. Total Harmonic Distortion vs Input Signal Amplitude

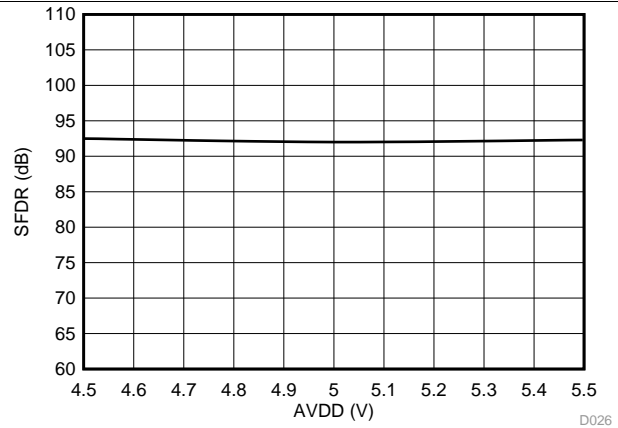


Figure 31. Spurious-Free Dynamic Range vs High-Side Supply Voltage

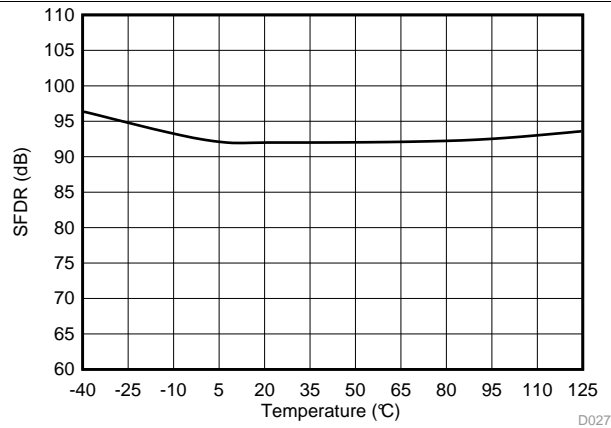


Figure 32. Spurious-Free Dynamic Range vs Temperature

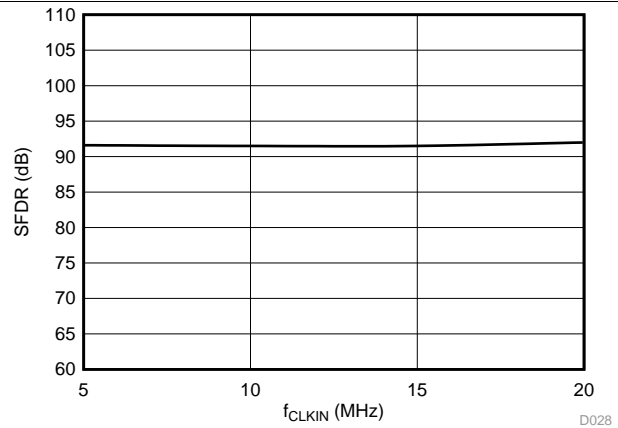


Figure 33. Spurious-Free Dynamic Range vs Clock Frequency

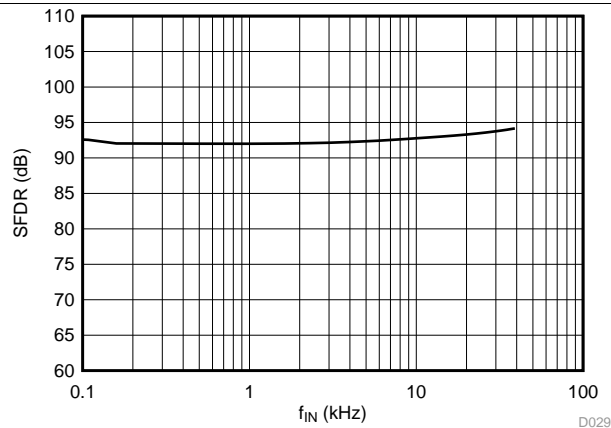


Figure 34. Spurious-Free Dynamic Range vs Input Signal Frequency

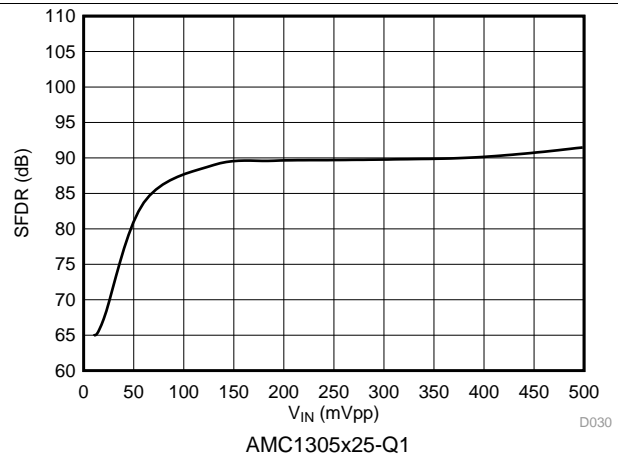
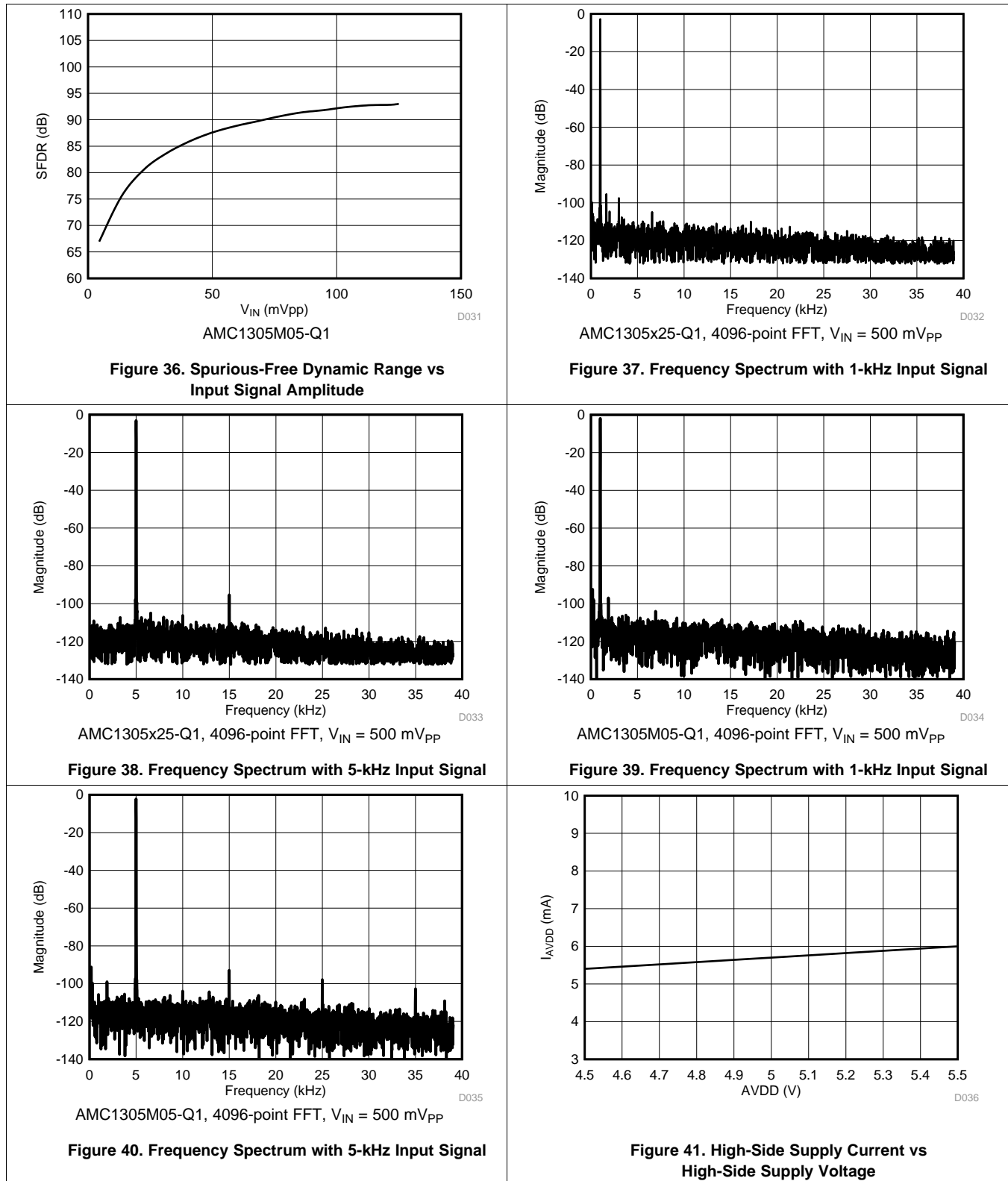


Figure 35. Spurious-Free Dynamic Range vs Input Signal Amplitude

Typical Characteristics (continued)

At $T_A = 25^\circ\text{C}$, $AV_{DD} = 5.0\text{ V}$, $DV_{DD} = 3.3\text{ V}$, $A_{INP} = -250\text{ mV to } 250\text{ mV}$, $A_{INN} = 0\text{ V}$, $f_{CLKIN} = 20\text{ MHz}$, and sinc³ filter with OSR = 256, unless otherwise noted.



Typical Characteristics (continued)

At $T_A = 25^\circ\text{C}$, $AVDD = 5.0\text{ V}$, $DVDD = 3.3\text{ V}$, $A\text{INP} = -250\text{ mV to }250\text{ mV}$, $A\text{INN} = 0\text{ V}$, $f_{\text{CLKIN}} = 20\text{ MHz}$, and sinc³ filter with OSR = 256, unless otherwise noted.

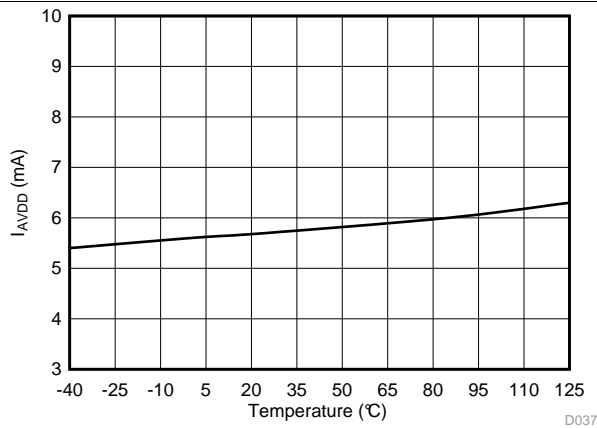


Figure 42. High-Side Supply Current vs Temperature

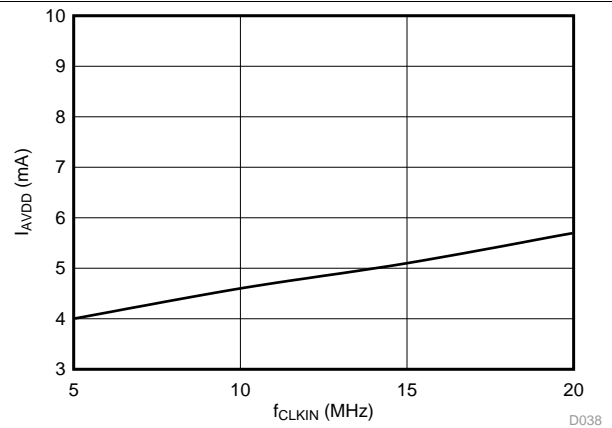


Figure 43. High-Side Supply Current vs Clock Frequency

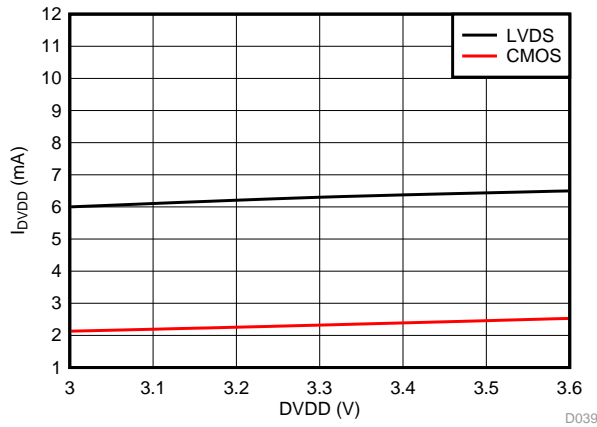


Figure 44. Controller-Side Supply Current vs Controller-Side Supply Voltage (3.3 V, nom)

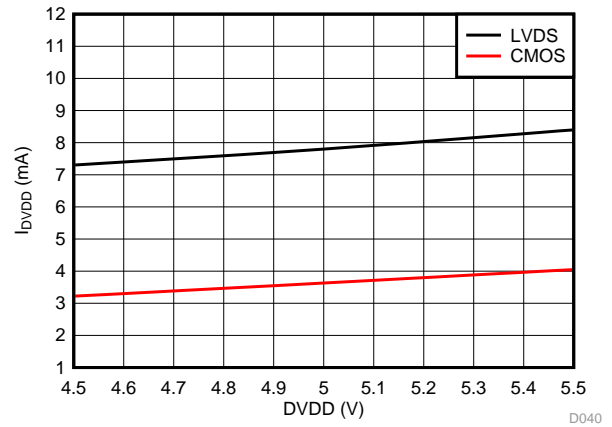


Figure 45. Controller-Side Supply Current vs Controller-Side Supply Voltage (5 V, nom)

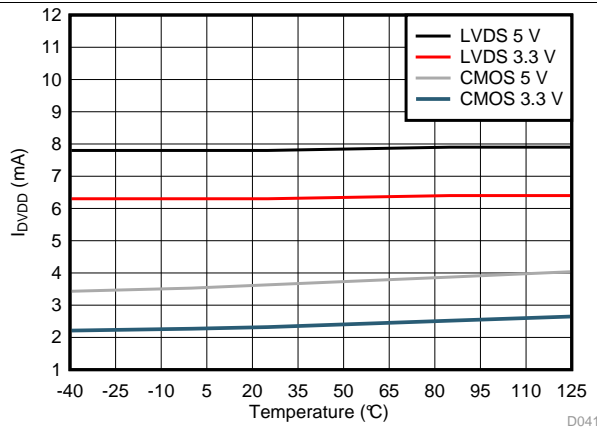


Figure 46. Controller-Side Supply Current vs Temperature

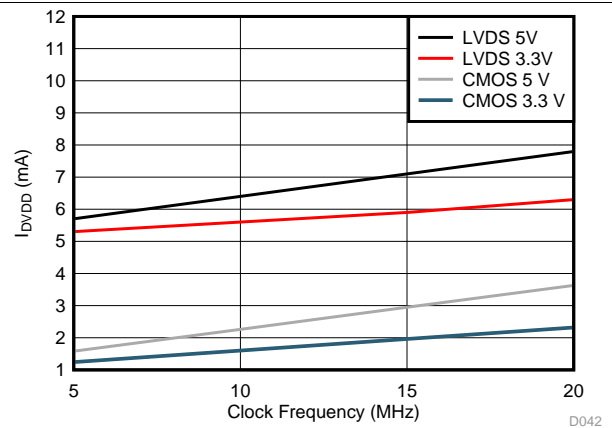


Figure 47. Controller-Side Supply Current vs Clock Frequency

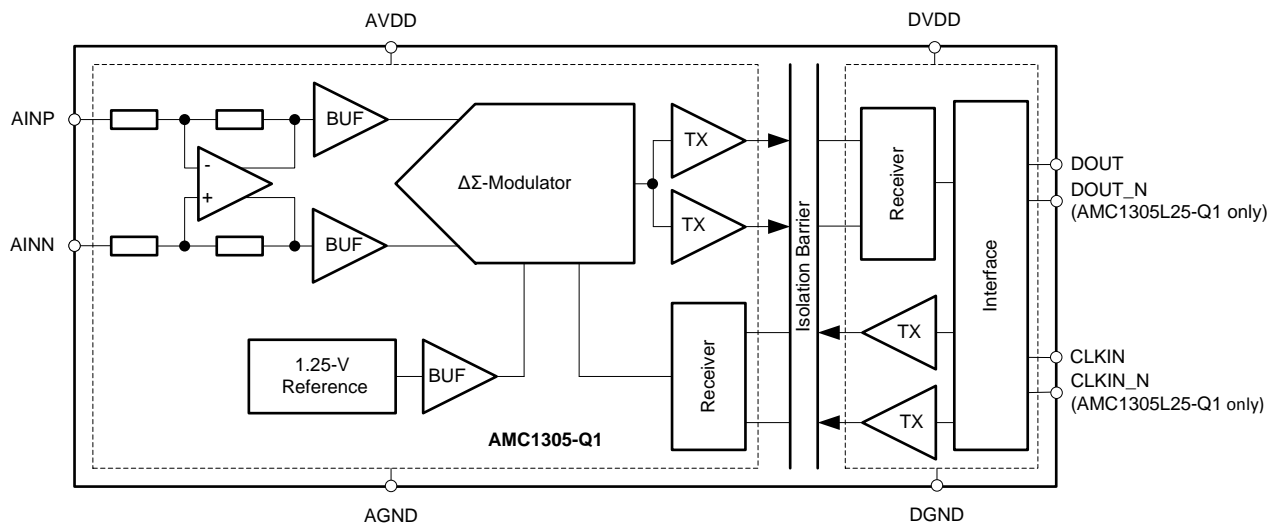
8 Detailed Description

8.1 Overview

The differential analog input (AINP and AINN) of the AMC1305-Q1 is a fully-differential amplifier feeding the switched-capacitor input of a second-order delta-sigma ($\Delta\Sigma$) modulator stage that digitizes the input signal into a 1-bit output stream. The isolated data output (DOUT) of the converter provides a stream of digital ones and zeros synchronous to the externally-provided clock source at the CLKIN pin with a frequency in the range of 5 MHz to 20.1 MHz. The time average of this serial bit-stream output is proportional to the analog input voltage.

The [Functional Block Diagram](#) section shows a detailed block diagram of the AMC1305-Q1. The analog input range is tailored to directly accommodate a voltage drop across a shunt resistor used for current sensing. The SiO₂-based capacitive isolation barrier supports a high level of magnetic field immunity as described in the application report [ISO72x Digital Isolator Magnetic-Field Immunity](#) (SLLA181A), available for download at www.ti.com. The external clock input simplifies the synchronization of multiple current-sense channels on the system level. The extended frequency range of up to 20.1 MHz supports higher performance levels compared to other solutions available on the market.

8.2 Functional Block Diagram



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8.3 Feature Description

8.3.1 Analog Input

The AMC1305-Q1 incorporates front-end circuitry that contains a differential amplifier and sampling stage, followed by a $\Delta\Sigma$ modulator. The gain of the differential amplifier is set by internal precision resistors to a factor of 4 for devices with a specified input voltage range of ± 250 mV (for the AMC1305x25-Q1), or to a factor of 20 for devices with a ± 50 -mV input voltage range (for the AMC1305M05-Q1), resulting in a differential input impedance of 5 k Ω (for the AMC1305M05-Q1) or 25 k Ω (for the AMC1305x25-Q1).

Consider the input impedance of the AMC1305-Q1 in designs with high-impedance signal sources that can cause degradation of gain and offset specifications. The importance of this effect, however, depends on the desired system performance. Additionally, the input bias current caused by the internal common-mode voltage at the output of the differential amplifier causes an offset that depends on the actual amplitude of the input signal. See the [Isolated Voltage Sensing](#) section for more details on reducing these effects.

There are two restrictions on the analog input signals (AINP and AINN). First, if the input voltage exceeds the range of AGND – 6 V to AVDD + 0.5 V, the input current must be limited to 10 mA because the device input electrostatic discharge (ESD) protection diodes turn on. In addition, the linearity and noise performance of the device are ensured only when the differential analog input voltage remains within the specified linear full-scale range (FSR), that is ± 250 mV (for the AMC1305x25-Q1) or ± 50 mV (for the AMC1305M05-Q1), and within the specified input common-mode range.

8.3.2 Modulator

The modulator implemented in the AMC1305-Q1 is a second-order, switched-capacitor, feed-forward $\Delta\Sigma$ modulator, such as the one conceptualized in [Figure 48](#). The analog input voltage V_{IN} and the output V_5 of the 1-bit digital-to-analog converter (DAC) are differentiated, providing an analog voltage V_1 at the input of the first integrator stage. The output of the first integrator feeds the input of the second integrator stage, resulting in output voltage V_3 that is differentiated with the input signal V_{IN} and the output of the first integrator V_2 . Depending on the polarity of the resulting voltage V_4 , the output of the comparator is changed. In this case, the 1-bit DAC responds on the next clock pulse by changing its analog output voltage V_5 , causing the integrators to progress in the opposite direction while forcing the value of the integrator output to track the average value of the input.

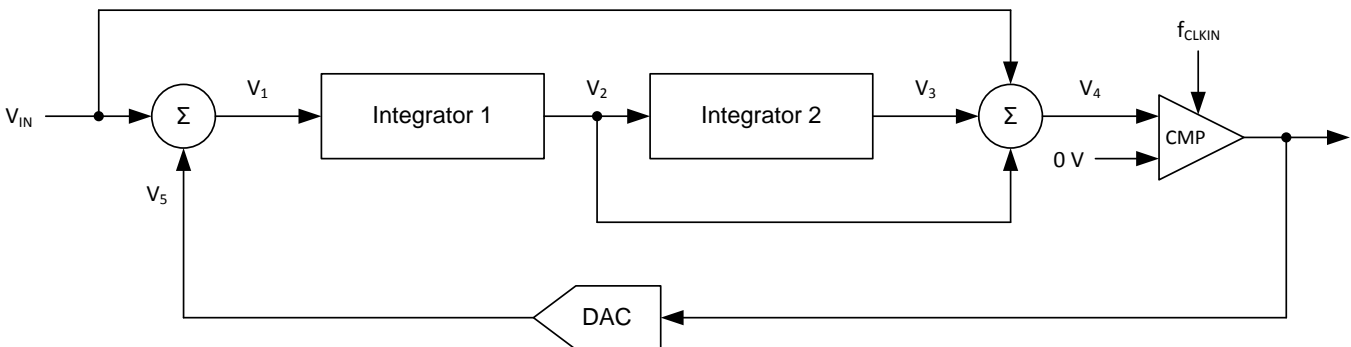


Figure 48. Block Diagram of a Second-Order Modulator

The modulator shifts the quantization noise to high frequencies; see [Figure 49](#). Therefore, use a low-pass digital filter at the output of the device to increase overall performance. This filter is also used to convert from the 1-bit data stream at a high sampling rate into a higher-bit data word at a lower rate (decimation). TI's microcontroller family [TMS320F2837x](#) offers a suitable programmable, hardwired filter structure termed a *sigma-delta filter module* (SDFM) optimized for usage with the AMC1305-Q1 family. Alternatively, a field-programmable gate array (FPGA) can be used to implement the digital filter.

Feature Description (continued)

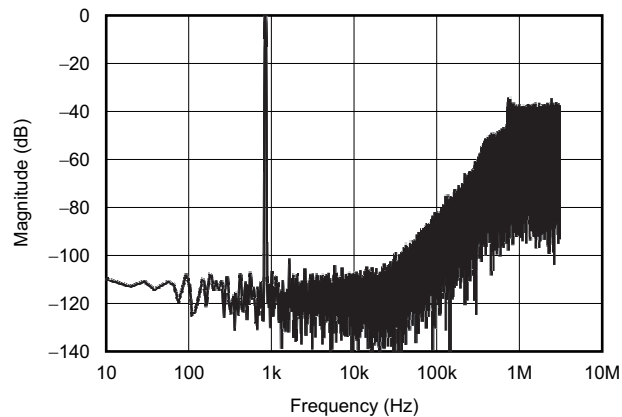


Figure 49. Quantization Noise Shaping

8.3.3 Digital Output

A differential input signal of 0 V ideally produces a stream of ones and zeros that are high 50% of the time. A differential input of 250 mV (for the AMC1305x25-Q1) or 50 mV (for the AMC1305M05-Q1) produces a stream of ones and zeros that are high 90% of the time. A differential input of –250 mV (–50 mV for the AMC1305M05-Q1) produces a stream of ones and zeros that are high 10% of the time. These input voltages are also the specified linear ranges of the different AMC1305-Q1 versions with performance as specified in this document. If the input voltage value exceeds these ranges, the output of the modulator shows non-linear behavior while the quantization noise increases. The output of the modulator would clip with a stream of only zeros with an input less than or equal to –312.5 mV (–62.5 mV for the AMC1305M05-Q1) or with a stream of only ones with an input greater than or equal to 312.5 mV (62.5 mV for the AMC1305M05-Q1). In this case, however, the AMC1305-Q1 generates a single 1 (if the input is at negative full-scale) or 0 every 128 clock cycles to indicate proper device function (see the [Fail-Safe Output](#) section for more details). The input voltage versus the output modulator signal is shown in [Figure 50](#).

The density of ones in the output bit-stream for any input voltage value (with the exception of a full-scale input signal as described in [Output Behavior in Case of Full-Scale Input](#)) can be calculated using [Equation 1](#):

$$\frac{V_{IN} + V_{Clipping}}{2 * V_{Clipping}} \tag{1}$$

The AMC1305-Q1 system clock is typically 20 MHz and is provided externally at the CLKIN pin. Data are synchronously provided at 20 MHz at the DOUT pin. Data change at the CLKIN falling edge. For more details, see the [Switching Characteristics](#) table.

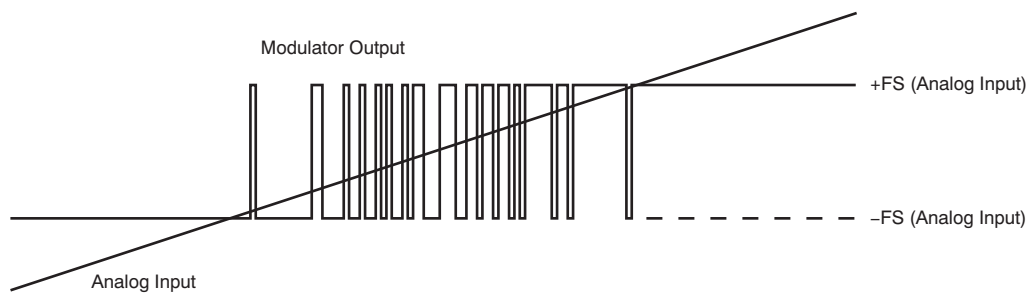


Figure 50. Analog Input versus AMC1305-Q1 Modulator Output

8.4 Device Functional Modes

8.4.1 Fail-Safe Output

In the case of a missing high-side supply voltage (AVDD), the output of a $\Delta\Sigma$ modulator is not defined and could cause a system malfunction. In systems with high safety requirements, this behavior is not acceptable. Therefore, the AMC1305-Q1 implements a fail-safe output function that ensures the device maintains its output level in case of a missing AVDD, as shown in Figure 51.

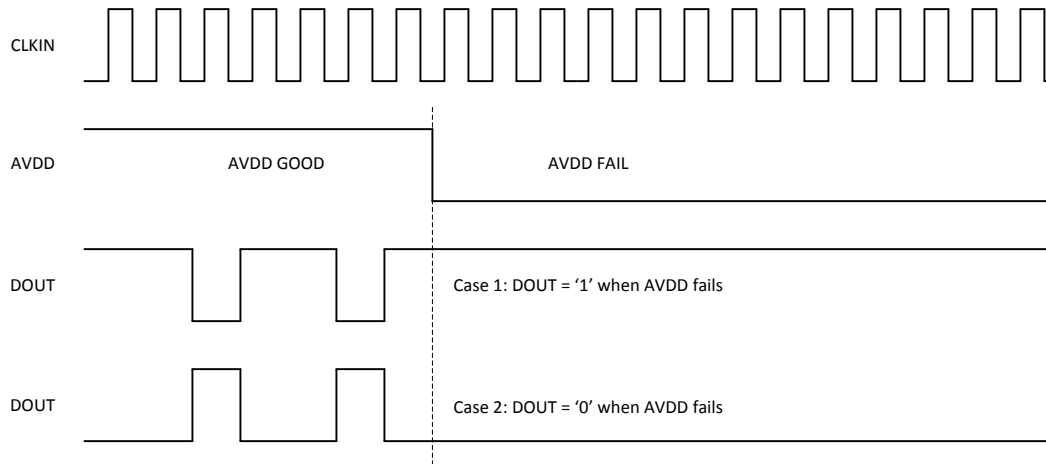


Figure 51. Fail-Safe Output of the AMC1305-Q1

8.4.2 Output Behavior in Case of Full-Scale Input

If a full-scale input signal is applied to the AMC1305-Q1 (that is, $V_{IN} \geq V_{Clipping}$), the device generates a single one or zero every 128 bits at DOUT, depending on the actual polarity of the signal being sensed, as shown in Figure 52.

In this way, differentiating between a missing AVDD and a full-scale input signal is possible on the system level.

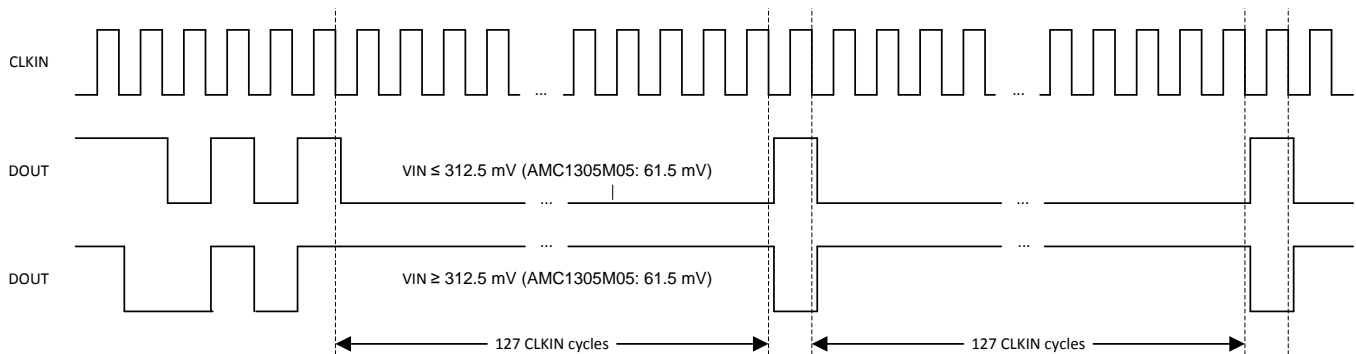


Figure 52. Overage Output of the AMC1305-Q1

9 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

9.1.1 Digital Filter Usage

The modulator generates a bit stream that is processed by a digital filter to obtain a digital word similar to a conversion result of a conventional analog-to-digital converter (ADC). A very simple filter, built with minimal effort and hardware, is a sinc³-type filter, as shown in [Equation 2](#):

$$H(z) = \left(\frac{1 - z^{-OSR}}{1 - z^{-1}} \right)^3 \quad (2)$$

This filter provides the best output performance at the lowest hardware size (count of digital gates) for a second-order modulator. All the characterization in this document is also done with a sinc³ filter with an over-sampling ratio (OSR) of 256 and an output word width of 16 bits.

$$SNR = 1.76dB + 6.02dB * ENOB \quad (3)$$

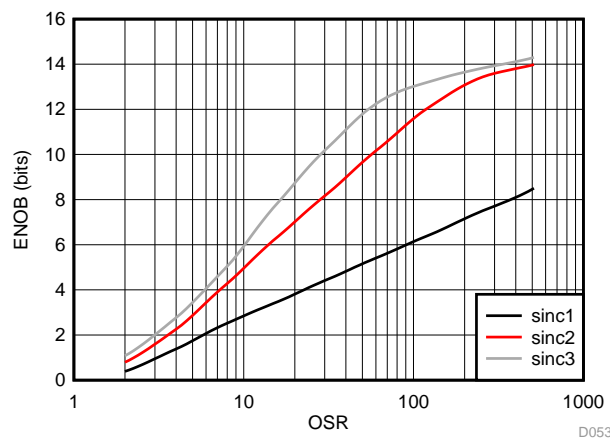


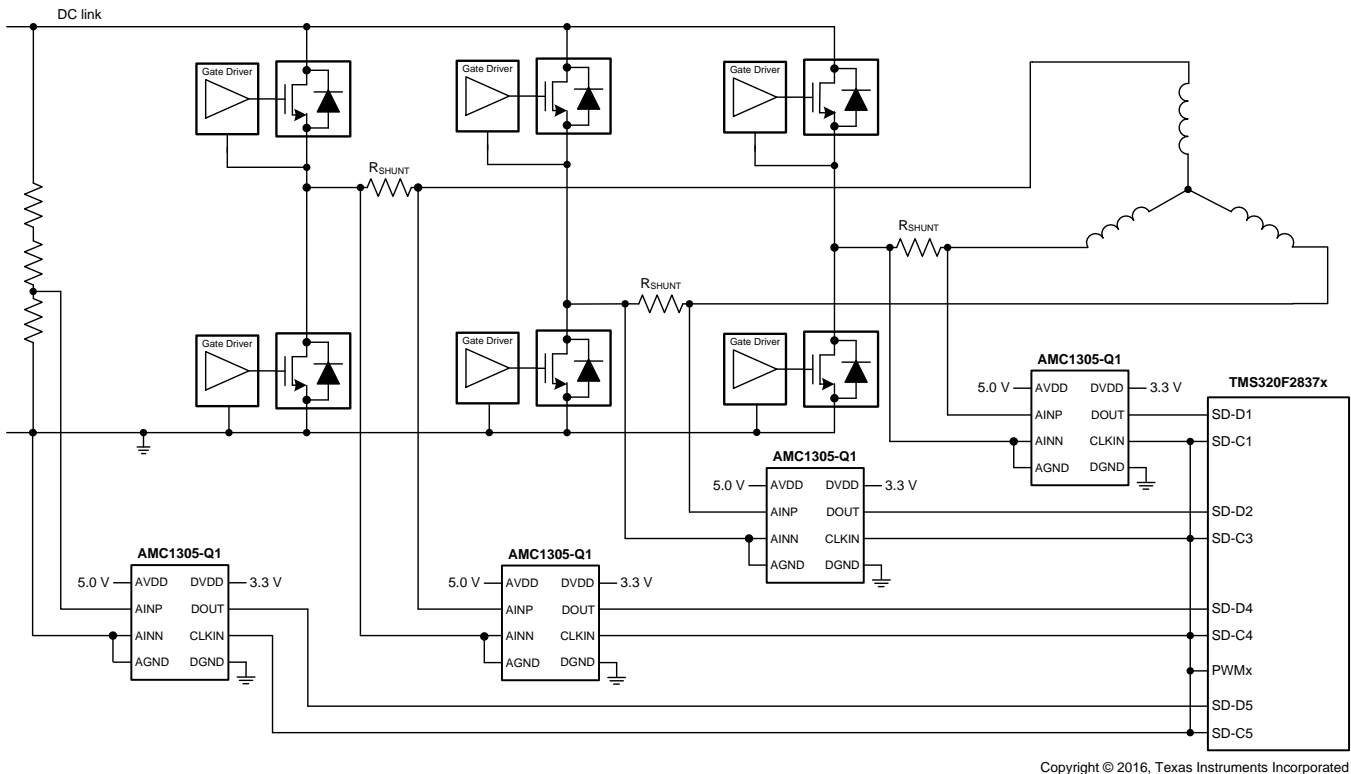
Figure 53. Measured Effective Number of Bits versus Oversampling Ratio

An example code for an implementation of a sinc³ filter in an FPGA, see the application note [Combining ADS1202 with FPGA Digital Filter for Current Measurement in Motor Control Applications \(SBAA094\)](#), available for download at www.ti.com.

9.2 Typical Applications

9.2.1 Traction Inverter Application

Because to their high ac and dc performance, isolated $\Delta\Sigma$ modulators are being widely used in new generation traction inverter designs. Traction inverters are critical parts of electrical and hybrid electrical vehicles. The input structure of the AMC1305-Q1 is optimized for use with low-impedance shunt resistors and is therefore tailored for isolated current sensing using shunts.



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Figure 54. The AMC1305-Q1 in a Traction Inverter Application

9.2.1.1 Design Requirements

A typical operation of the device in a traction inverter application is shown in Figure 54. When the inverter stage is part of a motor drive system, measurement of the motor phase current is done via the shunt resistors (R_{SHUNT}). Depending on the system design, either all three or only two phase currents are sensed.

In this example, an additional fourth AMC1305-Q1 is used to support isolated voltage sensing of the dc link. This high voltage is reduced using a high-impedance resistive divider before being sensed by the device across a smaller resistor. The value of this resistor can degrade the performance of the measurement, as described in the [Isolated Voltage Sensing](#) section.

9.2.1.2 Detailed Design Procedure

The usually recommended RC filter in front of a $\Delta\Sigma$ modulator to improve signal-to-noise performance of the signal path, is not required for the AMC1305-Q1. By design, the input bandwidth of the analog front-end of the device is limited to 1 MHz.

For modulator output bit-stream filtering, a device from TI's [TMS320F2837x](#) family of dual-core MCUs is recommended. This family supports up to eight channels of dedicated hardwired filter structures that significantly simplify system level design by offering two filtering paths per channel: one providing high accuracy results for the control loop and one fast response path for overcurrent detection.

Typical Applications (continued)

9.2.1.3 Application Curve

In motor control applications, a very fast response time for overcurrent detection is required. The time for fully settling the filter in case of a step-signal at the input of the modulator depends on its order; that is, a sinc³ filter requires three data updates for full settling (with $f_{\text{DATA}} = f_{\text{CLK}} / \text{OSR}$). Therefore, for overcurrent protection, filter types other than sinc³ can be a better choice; an alternative is the sinc² filter. [Figure 55](#) compares the settling times of different filter orders.

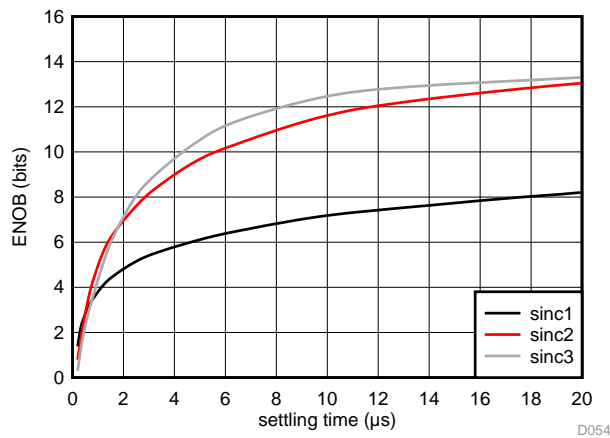


Figure 55. Measured Effective Number of Bits versus Settling Time

The delay time of the sinc filter with a continuous signal is half of its settling time.

Typical Applications (continued)

9.2.2 Isolated Voltage Sensing

The AMC1305-Q1 is optimized for usage in current-sensing applications using low-impedance shunts. However, the device can also be used in isolated voltage-sensing applications if the impact of the (usually higher) impedance of the resistor used in this case is considered.

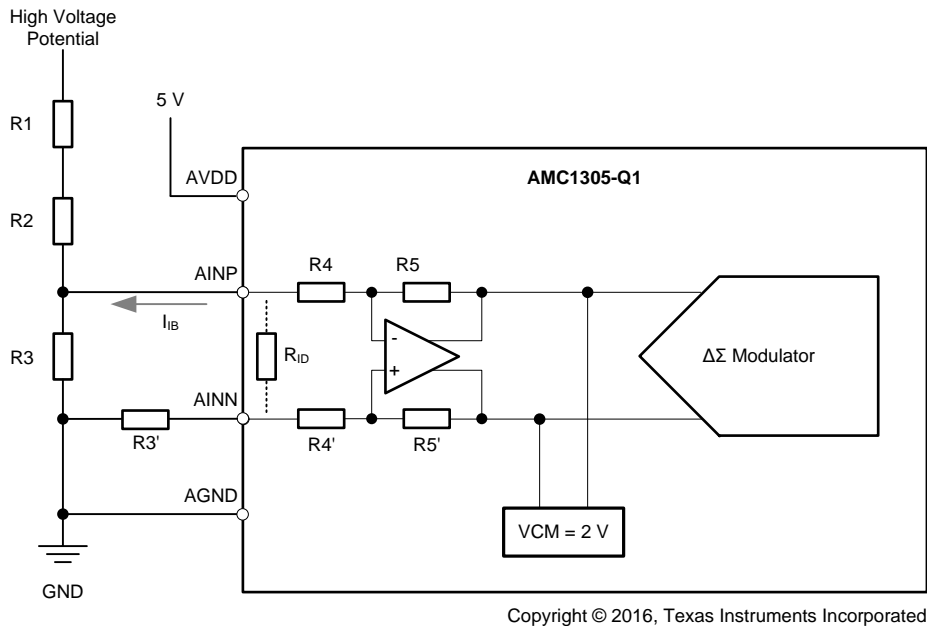


Figure 56. Using AMC1305-Q1 for Isolated Voltage Sensing

9.2.2.1 Design Requirements

Figure 56 shows a simplified circuit typically used in high-voltage sensing applications. The high impedance resistors (R1 and R2) are used as voltage dividers and dominate the current value definition. The resistance of the sensing resistor R3 is chosen to meet the input voltage range of the AMC1305-Q1. This resistor and the differential input impedance of the device (the AMC1305x25-Q1 is 25 kΩ, the AMC1305M05-Q1 is 5 kΩ) also create a voltage divider that results in an additional gain error. With the assumption of R1, R2, and R_{IN} having a considerably higher value than R3, the resulting total gain error can be estimated using Equation 4, with E_G being the gain error of the AMC1305-Q1.

$$|E_{G_{tot}}| = |E_G| + \frac{R_3}{R_{IN}} \quad (4)$$

This gain error can be easily minimized during the initial system level gain calibration procedure.

9.2.2.2 Detailed Design Procedure

As indicated in Figure 56, the output of the integrated differential amplifier is internally biased to a common-mode voltage of 2 V. This voltage results in a bias current I_{IB} through the resistive network R4 and R5 (or R4' and R5') used for setting the gain of the amplifier. The value range of this current is specified in the Electrical Characteristics table. This bias current generates additional offset error that depends on the value of the resistor R3. Because the value of this bias current depends on the actual common-mode amplitude of the input signal (as shown in Figure 57), the initial system offset calibration does not minimize its effect. Therefore, in systems with high accuracy requirements TI recommends using a series resistor at the negative input (AINN) of the AMC1305-Q1 with a value equal to the shunt resistor R3 (that is R3' = R3 in Figure 56) to eliminate the effect of the bias current.

Typical Applications (continued)

This additional series resistor ($R3'$) influences the gain error of the circuit. The effect can be calculated using Equation 5 with $R5 = R5' = 50 \text{ k}\Omega$ and $R4 = R4' = 2.5 \text{ k}\Omega$ (for the AMC1305M05-Q1) or $12.5 \text{ k}\Omega$ (for the AMC1305x25-Q1).

$$E_G(\%) = \left(1 - \frac{R4}{R4' + R3'} \right) * 100\% \quad (5)$$

9.2.2.3 Application Curve

Figure 57 shows the dependency of the input bias current on the common-mode voltage at the input of the AMC1305-Q1.

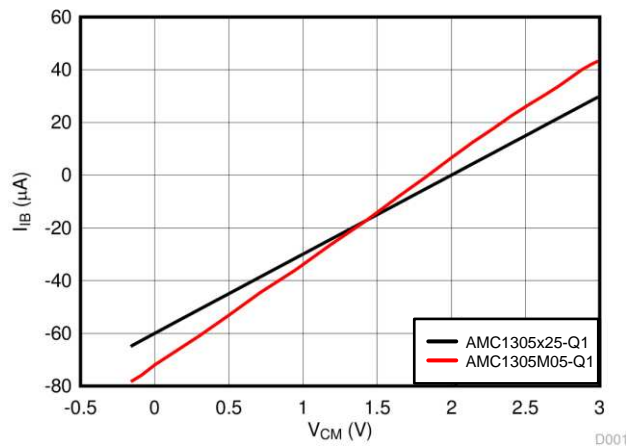


Figure 57. Input Current vs Input Common-Mode Voltage

10 Power-Supply Recommendations

In a typical traction inverter application, the high-side power supply (AVDD) for the device is derived from the floating power supply of the upper gate driver. For lowest cost, a Zener diode can be used to limit the voltage to $5\text{ V} \pm 10\%$. Alternatively a low-cost low-drop regulator (LDO), for example the [LP2951-xx-Q1](#), can be used to minimize noise on the power supply. A low-ESR decoupling capacitor of $0.1\ \mu\text{F}$ is recommended for filtering this power-supply path. Place this capacitor (C_2 in [Figure 58](#)) as close as possible to the AVDD pin of the AMC1305-Q1 for best performance. If better filtering is required, an additional $10\text{-}\mu\text{F}$ capacitor can be used. The floating ground reference (AGND) is derived from the end of the shunt resistor, which is connected to the negative input (AINN) of the device. If a four-pin shunt is used, the device inputs are connected to the inner leads, while AGND is connected to one of the outer leads of the shunt.

For decoupling of the digital power supply on controller side, TI recommends using a $0.1\text{-}\mu\text{F}$ capacitor assembled as close to the DVDD pin of the AMC1305-Q1 as possible, followed by an additional capacitor in the range of $1\ \mu\text{F}$ to $10\ \mu\text{F}$.

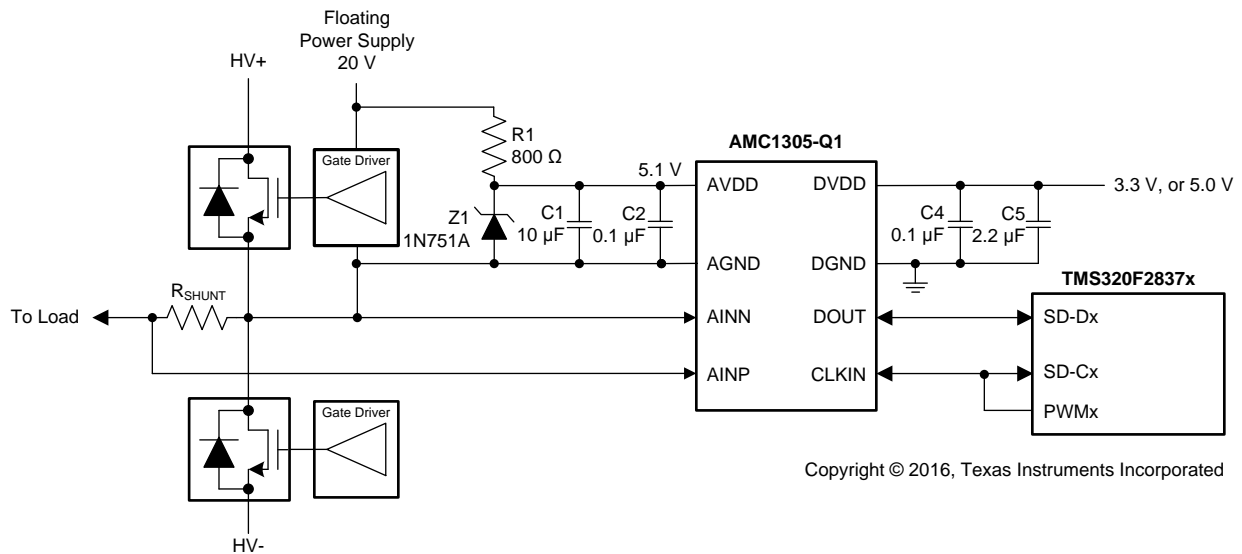


Figure 58. Zener-Diode-Based High-Side Power Supply

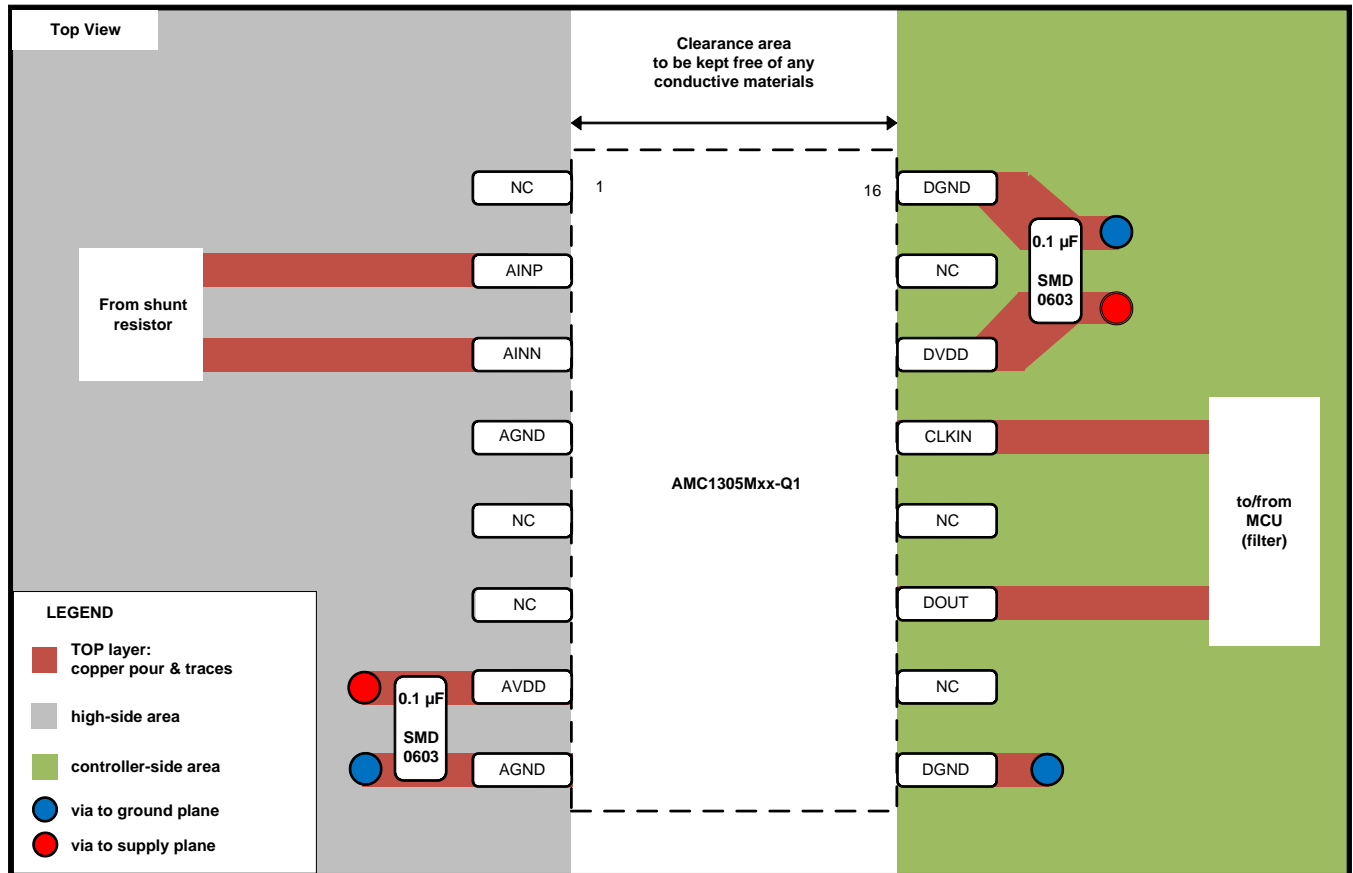
11 Layout

11.1 Layout Guidelines

A layout recommendation showing the critical placement of the decoupling capacitors (as close as possible to the AMC1305-Q1) and placement of the other components required by the device is shown in [Figure 59](#).

For the AMC1305L25-Q1 version, place the 100-Ω termination resistor as close as possible to the CLKIN, CLKIN_N inputs of the device to achieve highest signal integrity. If not integrated, an additional termination resistor is required as close as possible to the LVDS data inputs of the MCU or filter device; see [Figure 60](#).

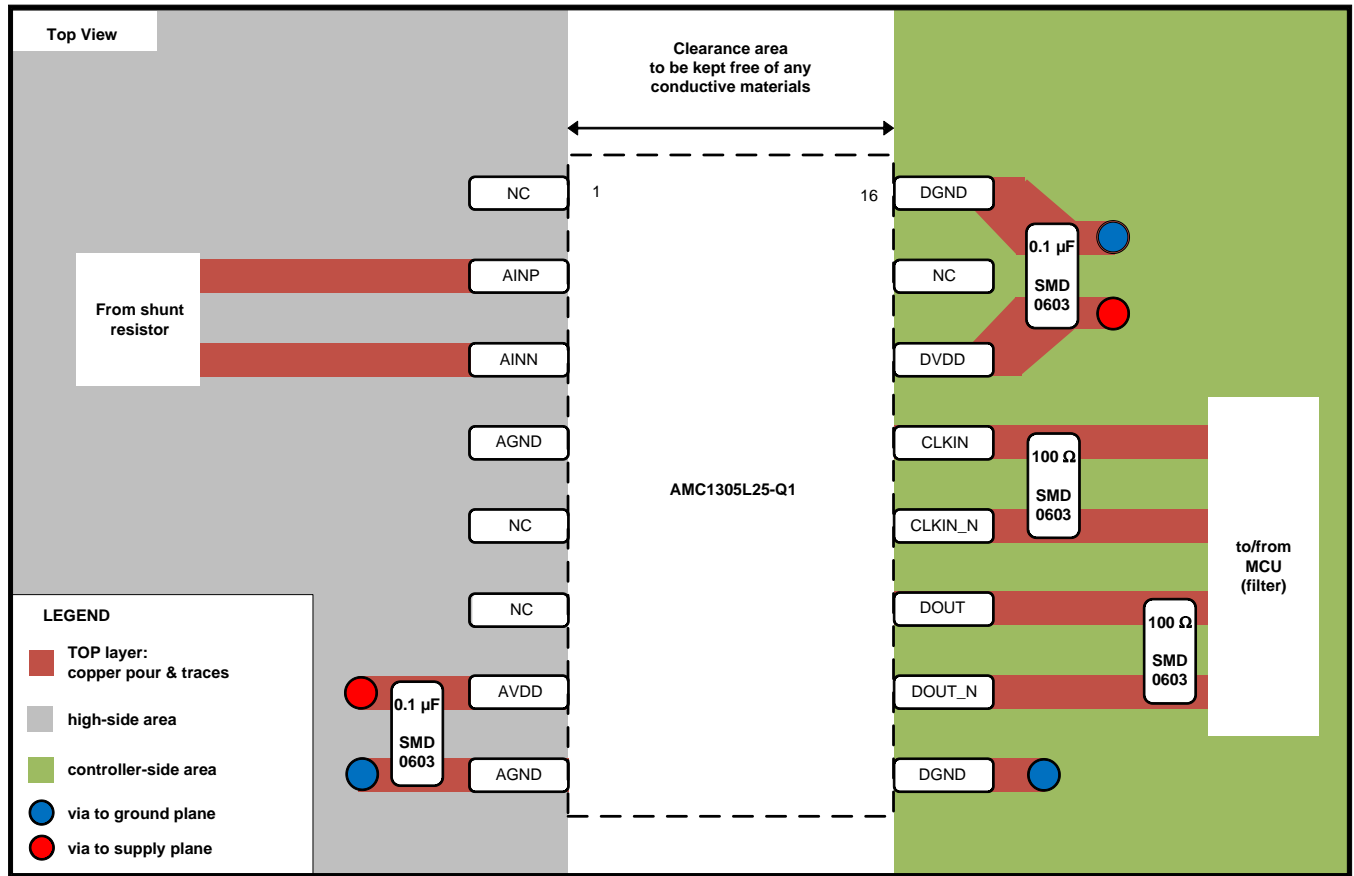
11.2 Layout Examples



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Figure 59. Recommended Layout of the AMC1305Mxx-Q1

Layout Examples (continued)



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Figure 60. Recommended Layout of the AMC1305L25-Q1

12 Device and Documentation Support

12.1 Documentation Support

12.1.1 Related Documentation

For related documentation see the following:

- [Isolation Glossary](#)
- [ISO72x Digital Isolator Magnetic-Field Immunity](#)
- [Combining ADS1202 with FPGA Digital Filter for Current Measurement in Motor Control Applications](#)
- [LP2951-xx-Q1 Adjustable Micropower Voltage Regulators With Shutdown](#)
- [TMS320F2837xD Dual-Core Delfino™ Microcontrollers](#)

12.2 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to order now.

Table 1. Related Links

| PARTS | PRODUCT FOLDER | ORDER NOW | TECHNICAL DOCUMENTS | TOOLS & SOFTWARE | SUPPORT & COMMUNITY |
|---------------|----------------------------|----------------------------|----------------------------|----------------------------|----------------------------|
| AMC1305L25-Q1 | Click here | Click here | Click here | Click here | Click here |
| AMC1305M05-Q1 | Click here | Click here | Click here | Click here | Click here |
| AMC1305M25-Q1 | Click here | Click here | Click here | Click here | Click here |

12.3 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

12.4 Community Resource

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

TI E2E™ Online Community *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

12.5 Trademarks

E2E is a trademark of Texas Instruments.
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12.6 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

12.7 Glossary



SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|-------------------------|----------------------|--------------|-------------------------|---|
| AMC1305L25QDWQ1 | PREVIEW | SOIC | DW | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | -40 to 125 | 1305L25Q1 | |
| AMC1305L25QDWRQ1 | PREVIEW | SOIC | DW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | -40 to 125 | 1305L25Q1 | |
| AMC1305M05QDWQ1 | PREVIEW | SOIC | DW | 16 | 40 | TBD | Call TI | Call TI | -40 to 125 | | |
| AMC1305M05QDWRQ1 | PREVIEW | SOIC | DW | 16 | 2000 | TBD | Call TI | Call TI | -40 to 125 | | |
| AMC1305M25QDWQ1 | ACTIVE | SOIC | DW | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | -40 to 125 | 1305M25Q1 |  |
| AMC1305M25QDWRQ1 | ACTIVE | SOIC | DW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR | -40 to 125 | 1305M25Q1 |  |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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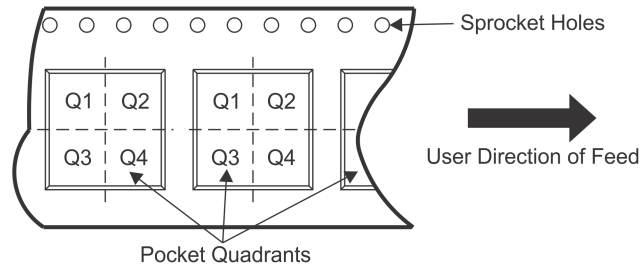
OTHER QUALIFIED VERSIONS OF AMC1305L25-Q1, AMC1305M05-Q1, AMC1305M25-Q1 :

- Catalog: [AMC1305L25](#), [AMC1305M05](#), [AMC1305M25](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| AMC1305M25QDWRQ1 | SOIC | DW | 16 | 2000 | 330.0 | 16.4 | 10.75 | 10.7 | 2.7 | 12.0 | 16.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|------------------|--------------|-----------------|------|------|-------------|------------|-------------|
| AMC1305M25QDWRQ1 | SOIC | DW | 16 | 2000 | 367.0 | 367.0 | 38.0 |

DW (R-PDSO-G16)

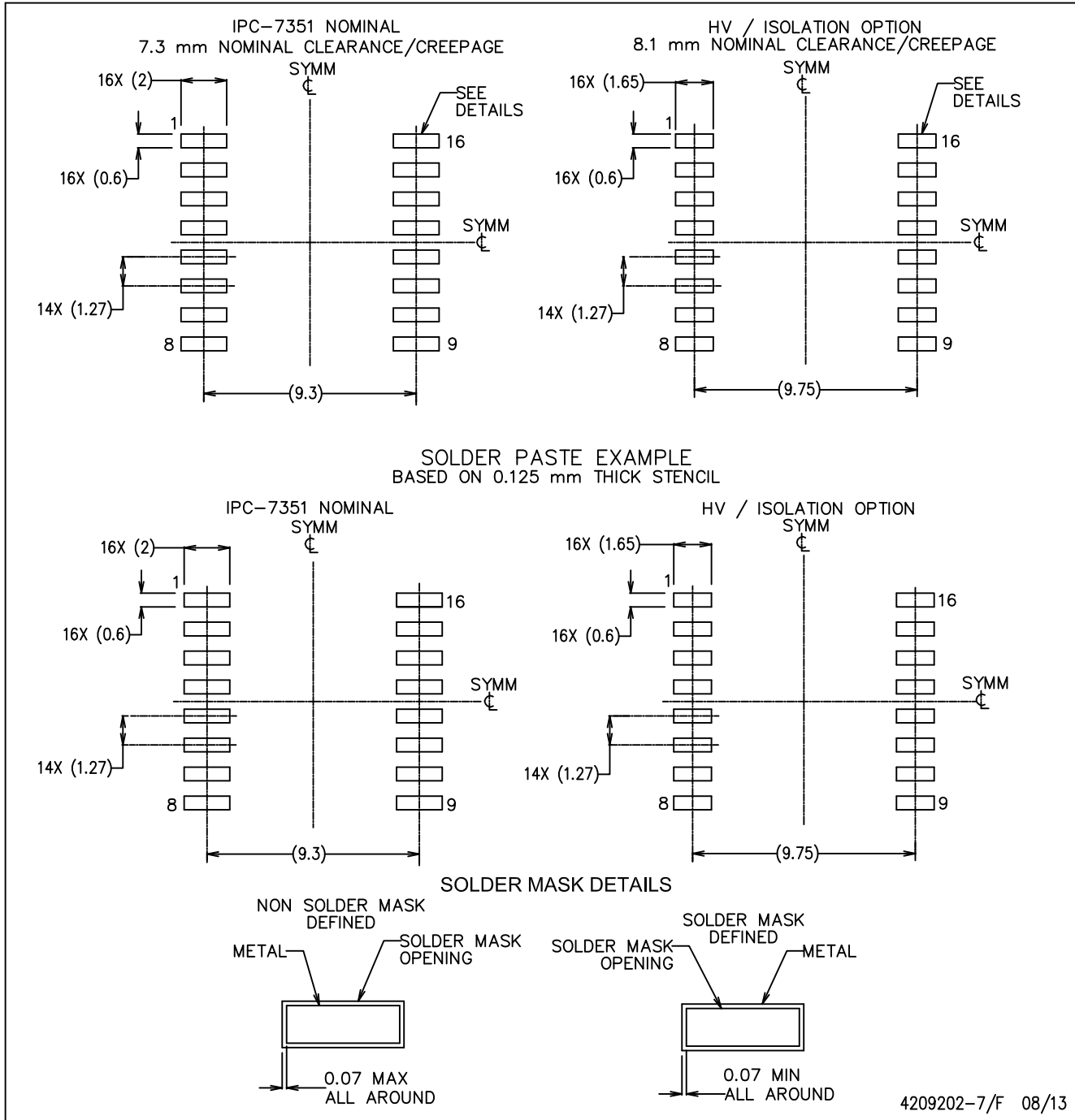
PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - Falls within JEDEC MS-013 variation AA.

DW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4209202-7/F 08/13

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Refer to IPC7351 for alternate board design.
 - D. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
 - E. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
 - F. Board assembly site may have different recommendations for stencil design.

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